

6 + 3 Channels DC-DC PMU with Li-ion Battery Charger for CMOS DSC/DV

General Description

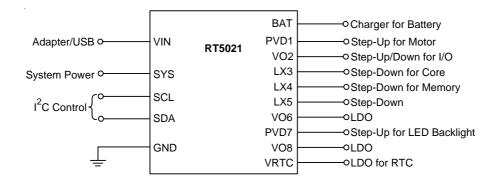
The RT5021 is a complete power supply solution for digital still cameras and other hand held devices. The RT5021 is composed of a multi-channel DC-DC power converter unit, a single-cell linear Li-ion battery charger, a charger type detector, and an I²C control interface.

The power converter unit includes one synchronous stepup converter (CH1), one synchronous step-up/down converter (CH2), three synchronous step-down converters (CH3/4/5), two LDOs with input power as low as 1.5V (CH6/8), one WLED driver in synchronous high-voltage step-up mode or low-voltage current regulator mode (CH7), and a keep-alive LDO (CH9) for RTC application. All converters are internally frequency compensated and integrate power MOSFETs. The power converter unit provides complete protection functions : over current, thermal shutdown, over voltage, and under voltage protection. RT5021 has a WAKEUP impulse generation circuitry to monitor VIN or BAT installation event. To fulfill most of applications, RT5021 has six preset power on/off sequences.

The battery charger includes Auto Power Path Management (APPM). No external MOSFETs are required. The charger can enter sleep mode when power is removed. Charging tasks are optimized by using a control algorithm to vary the charge rate, including pre-charge mode, fast charge mode and constant voltage mode. The charge current can also be programmed via the I²C control interface. The battery regulation voltage and current can be adjusted by JEITA standard temperature control or other schemes set via the I²C interface. The internal thermal feedback circuitry regulates the die temperature to optimize the charge rate for all ambient temperatures. The charging task will always be terminated in constant voltage mode when the charging current reduces to the termination current of 10% x I_{CHG_FAST}. The charger includes under voltage and over voltage protection for the supply input voltage, VIN. The charger includes USB charger detection circuitry via D+ and D- pins of USB interface to detect USB standard downstream ports (SDP), USB charging downstream port (CDP), dedicated charger port (DCP), or Apple/Sony charger ports. RT5021 uses some indicators to show charger states: two open drain ports CHG and CHG2, and an interrupt (INT) to immediately notify the state change.

RT5021 has I²C interface to control rich functions of Power Converter Unit and Charger Unit. The RT5021 is available in the WQFN-40L 5x5 package.

Simplified Application Circuit





Features

Power Converter Unit

- CH1 LV Sync Step-Up
 - ► Support Up to 1A Loading, DVS (Dynamic Voltage Scaling), Load-Disconnect, Up to 95% Efficiency, PSM/PWM Selectable
- CH2 LV Sync Step-Up/Down
 - ▶ Support Up to 1A Loading, DVS, Up to 95% Efficiency, PSM/PWM Selectable
- CH3/4 LV Sync Step-Down
 - ➤ Support Up to 1.3A Loading, DVS, Up to 95% Efficiency, 100% (MAX) Duty Cycle, PSM/PWM Selectable
- CH5 LV Sync Step-Down
 - Support Up to 0.6A Loading, Up to 95% Efficiency, 100% (MAX) Duty Cycle
 - Output Voltage can be Selected from Preset List or Set by External Feedback Network
- CH6 Low Input Power LDO
 - ▶ V_{IN} Range 1.5V to 5.5V
 - ▶ Output Voltage Level Selectable in I²C Register
- CH7 WLED Driver in Either Sync Step-Up Operation or Current Regulator Operation
 - Step-Up Mode with LED Open Protection (OVP7 16V or 25V, Selectable in I²C Register)
 - ▶ Step-Up Mode Support Series 2 to 6 WLED and Load Disconnect Function
 - **▶ Current Regulator Mode for 1 WLED**
 - ▶ 31 WLED Dimming Levels
 - Automatic Mode Selection by External Circuit Topology
- CH8 Generic LDO
 - ▶ V_{IN} Range 1.5V to 5.5V
 - ▶ Output Voltage Level Selectable in I²C Register
- CH9 Low Quiescent LDO with Reverse Leakage Prevention for RTC Power Supply
 - Fixed 3.05V Output
- Six Preset Power On/Off Sequences by One Pin SEQ
 - ▶ SEQ # 0 : CH2→CH3→CH4
 - ► SEQ #1: CH1→CH3→CH2→CH4
 - ightharpoonup SEQ # 2 : CH1ightharpoonupCH3ightharpoonupCH4ightharpoonupCH2
 - ► SEQ # 3 : CH1→CH2→CH4→CH3

- ► SEQ # 4 : CH1→CH4→CH3→CH2
- ► SEQ # 5 : CH1→CH4→CH2→CH3
- All Power Switches Integrated with Internal Compensation
- Discharge Output of Every Channels when Turning Off
- Wake Up Impulse to Monitor BAT and VIN Plug-In
- Fixed 2MHz Switching Frequency for CH1/3/4/5,
 Fixed 1MHz Switching Frequency for CH2/7

Charger Unit

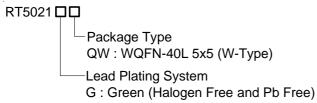
- 28V Maximum Rating for VIN Power
- Selectable Power Input Current Limit (0.1A / 0.5A / 1A / 1.5A)
- Auto Power Path Management (APPM) with Integrated Power MOSFETs
- Battery Charging Current Control and Regulation
 Voltage Control
- Programmable Charging Current and Safe Charge Timer
- Optimized Charge Rate Via Thermal Feedback
- Under Voltage Protection, Over Voltage Protection
- Charger Status and VIN Power GOOD Indicators
- Interrupt Indicator to JEITA Temperature/Fault/ Status Events when PMU is Enabled
 - **▶** Battery Temperature Events
 - ▶ Battery Removing Event
 - ▶ Charger in Thermal Regulation Control
 - ▶ Safety Timer Timeout
 - ▶ End of Charging
 - **▶ VIN Power Good**
 - ▶ VIN < DPM Threshold 4.35V</p>
 - ▶ Charger Type Detection Finishing
- Charger Type Detection
 - Dedicated Charger : Support Apple and Sony Charger
 - ▶ Secondary Charger Detection to Distinguish CDP and DCP
- I²C Control Interface : Support Fast Mode up to 400kb/s
- Small 40-Lead WQFN Package
- RoHS Compliant and Halogen Free



Applications

- DSC Power Supply System
- CMOS-Sensor DV
- Portable Instruments

Ordering Information

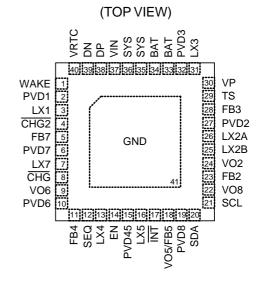


Note:

Richtek products are:

- ▶ RoHS compliant and compatible with the current requirements of IPC/JEDEC J-STD-020.
- ▶ Suitable for use in SnPb or Pb-free soldering processes.

Pin Configuration



WQFN-40L 5x5

Marking Information

RT5021 **GQW YMDNN**

RT5021GQW: Product Code

YMDNN: Date Code

Part Status

Part No.	Status	Package Type	Lead Plating System
RT5021GQW	EOL	WQFN-40L 5x5	Green (Halogen Free and Pb Free)

The part status values are defined as below:

Active: Device is in production and is recommended for new designs.

Lifebuy: The device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs.

Preview: Device has been announced but is not in production.

EOL: Richtek has discontinued the production of the device.

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Functional Pin Description

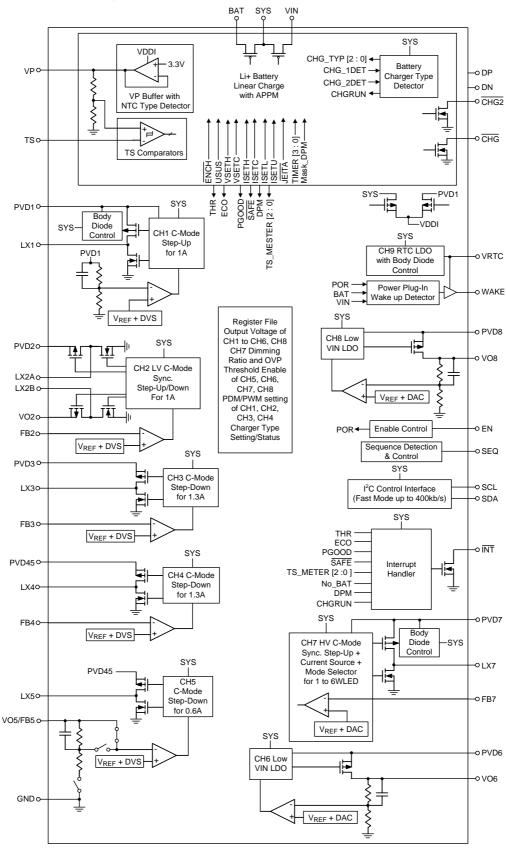
Pin No.	Pin Name	Pin Function
1	WAKE	Wake-Up Impulse Push Pull Output. If VIN or BAT plug in, WAKE pin generates one 90ms-width high pulse to notify micro processor.
2	PVD1	Power Output pin of CH1. To make CH1 stable, the power path from the pin PVD1 to its output capacitors must be as short (≤ 1 mm is better) and wide as possible to reduce its parasitic inductance. The output capacitor must be ceramic capacitor ($\geq 20 \mu F$).
3	LX1	Switch Node of CH1.
4	CHG2	2nd Charger Status Indicator (Open Drain Output).
5	FB7	Feedback Input Pin of CH7 in Step-Up Mode or Current Regulator Mode
6	PVD7	Power Output Pin of CH7 in Step-Up or Power Input Pin of CH7 in Current Regulator Mode.
7	LX7	Switch Node of CH7 in Step-Up Mode. LX7 initial voltage determine CH7 operation mode.
8	CHG	Charger Status Indicator (Open Drain Output).
9	VO6	Power Output Pin of CH6.
10	PVD6	Power Input Pin of CH6.
11	FB4	Feedback Input Pin of CH4.
12	SEQ	Power Sequence Selection for CH1 to CH4.
13	LX4	Switch Node of CH4.
14	EN	Enable Pin of Power Converter Unit.
15	PVD45	Power Input Pin of CH4 and CH5. To avoid the crosstalk between CH4 and CH5, the power path from the pin PVD45 to its input capacitors must be as short (≤ 1 mm is better) and wide as possible to reduce its parasitic inductance. The input capacitance must be $\geq 10 \mu F$ with low ESR.
16	LX5	Switch Node of CH5.
17	ĪNT	Interrupt Indicator Open Drain Output. If events of NoBAT, THR, EOC, Battery Temperature Change (TS_METER), PGOOD, SAFE, VIN DPM, or Charge Type Detection Finishing (CHGRUN) happen, the output INT goes low and the INT bit in I ² C register bank 0x9 is set to be "1". After INT bit is written to be "0", INT goes high.
18	VO5/FB5	Output Voltage Sense Pin or feedback network input pin of CH5. The function is selected by I ² C register.
19	PVD8	Power Input Pin of CH8.
20	SDA	Data Signal Pin of I ² C Interface.
21	SCL	Clock Signal Pin of I ² C Interface.
22	VO8	Power Output Pin of CH8.
23	FB2	Feedback Input Pin of CH2.
24	VO2	Power Output Pin of CH2.
25	LX2B	Switch Node B of CH2.
26	LX2A	Switch Node A of CH2.
27	PVD2	Power Input Pin of CH2.



Pin No.	Pin Name	Pin Function
28	FB3	Feedback Input Pin of CH3.
29	TS	Temperature Sense Input. The TS pin connects to a battery's thermistor to determine if the battery is too hot or too cold to charge. If the battery's temperature is out of range, charging is paused until it re-enters the valid range. TS also detects whether the battery (with NTC) is present or not.
30	VP	Power Output Pin of 3.3V Buffer for Battery Temperature Sensing.
31	LX3	Switch Node of CH3.
32	PVD3	Power Input Pin of CH3.
33, 34	BAT	Charger Output for Battery.
35, 36	SYS	Power Output for System. Connect this pin to System with a minimum $10\mu\text{F}$ ceramic capacitor to GND.
37	VIN	Supply Voltage Input.
38	DP	USB D+ Input for Charger Type Detection.
39	DN	USB D- Input for Charger Type Detection.
40	VRTC	RTC LDO Power Output Pin.
41 (Exposed pad)	GND	Exposed PAD Should be Soldered to PCB and Connected to GND.



Functional Block Diagram





Operation

The RT5021 is an integrated power solution for digital still cameras and other small handheld devices. It includes six DC-DC converters, a WLED driver, a RTC LDO, and a fully integrated single-cell Li-ion battery charger.

CH1: Step-Up DC-DC Converter

CH1 is a step-up converter for motor driver power. The converter operates at PFM or PWM current mode which can be set by I²C interface.

CH2: Step-Up/Down DC-DC Converter

CH2 is a step-up/down converter for I/O power. The converter operates at PFM or PWM current mode which can be set by I²C interface.

CH3: Step-Down DC-DC Converter

CH3 is a step-down converter for core power. The converter operates at PFM or PWM current mode which can be set by I2C interface.

CH4: Step-Down DC-DC Converter

CH4 is a step-down converter for memory power. The converter operates at PFM or PWM current mode which can be set by I²C interface.

CH5: Step-Down DC-DC Converter

CH5 is a step-down converter. The converter operates at PFM/PWM current mode.

CH6: Generic LDO

CH6 is a generic low voltage LDO for multiple purpose power.

CH7: WLED Driver

CH7 is a WLED driver that can operate in either current source mode or synchronous step-up mode which is determined by I²C interface control signal.

CH8: Generic LDO

CH8 is a generic low voltage LDO for multiple purpose power.

CH9: Keep Alive LDO and RTC

CH9 is a LDO providing a 3.05V output for real time clock.

Charger Unit

A Li-ion battery charger with automatic power path management is designed to operate in below modes.

Pre-Charge Mode

When the output voltage is lower than 2.8V, the charging current will be reduced to a ratio of fast-charge current set by A8.ISETA [3:0] to protect the battery life-time.

Fast-Charge Mode

When the output voltage is higher than 3V, the charging current will be equal to the fast-charge current set by A8.ISETA [3:0].

Constant Voltage Mode

When the output voltage is near 4.2V and the charging current falls below the termination current for a deglitch time of 25ms, the charger will be turned off and CHG will go to high.

Re-Charge Mode

When the chip is in charge termination mode, the charging current gradually goes down to zero. Once the battery voltage drops to below 4.1V for 100ms, the charger will resume charging operation.

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Absolute Maximum Ratings (Note 1)

• Supply Voltages, SYS	-0.3V to 6V
Supply Input Voltage, VIN	-0.3V to 28V
• Switch Node Voltage, LX1, LX2, LX3, LX4, LX5	-0.3V to 6V
• PVD7, LX7	-0.3V to 25V
• CHG	-0.3V to 28V
• CHG2	-0.3V to 6V
• Other Pins	-0.3V to 6V
• INT, CHG, CHG2 Continuous Current	20mA
BAT Continuous Current (Total in two pins)	2.5A
 Power Dissipation, P_D @ T_A = 25°C 	
WQFN-40L 5x5	3.64W
Package Thermal Resistance (Note 2)	
WQFN-40L 5x5, θ_{JA}	27.5°C/W
WQFN-40L 5x5, θ_{JC}	6°C/W
• Junction Temperature	150°C
• Lead Temperature (Soldering, 10 sec.)	260°C
Storage Temperature Range	-65°C to 125°C
ESD Susceptibility (Note 3)	
HBM (Human Body Model)	
MM (Machine Model)	200V
Recommended Operating Conditions (Note 4)	

Supply Input Voltage, BAT	- 1.8V to 5.5V
• Supply Input Voltage Range, VIN (A7.ISETL = 1)	- 4.4V to 6V
• Supply Input Voltage Range, VIN (A7.ISETL = 0)	- 4.5V to 6V
Junction Temperature Range	- −40°C to 125°C

• Ambient Temperature Range ----- ---- -40°C to 85°C

Electrical Characteristics

Power Converter Unit:

($V_{SYS} = 3.3V$, $T_A = 25$ °C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit	
Supply Voltage							
PMU Startup Voltage at SYS	V _{ST}	For bootstrap	1.5			V	
SYS Operating Voltage for PMU	V_{SYS}		2.7		5.5	V	
VDDI Over Voltage Protection (OVP) (Hysteresis High)			5.82	6	6.18	V	
VDDI OVP Hysteresis (Gap)				-0.25		V	
VDDI UVLO (Hysteresis High)		VDDI UVLO takes effect once CH2 soft-start finish	2.2	2.4	2.6	V	
VDDI UVLO Hysteresis (Gap)				-0.3		V	



Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Supply Current					•	
Shutdown Supply Current into BAT (Include I _{DDQ} of RTC LDO)	l _{OFF-BAT}	EN = L, and PMU off, BAT = 4.2V		10	20	μА
CH1 + CH2 + CH3 + CH4 Supply Current	I _{Q1234}	Non switching, EN = 3.3V			2000	μΑ
CH5 Supply Current	I_{Q5}	Non switching, A2.EN5 = 1			500	μΑ
CH6 Supply Current	I _{Q6}	A2.EN6 = 1	-		100	μΑ
CH7 in Step-Up Mode Supply Current	I _{Q7b}	Non switching, A2.EN7_DIM7 [4:0] = 5'b11111	1		500	μА
CH7 in Current Source mode Supply Current	I _{Q7c}	A2.EN7_DIM7 [4:0] = 5'b11111 PVD7 = 5V	ı		400	μА
CH8 Supply Current	I _{Q8}	A2.EN8 = 1	-		100	μΑ
Oscillator						
CH1, 3, 4, 5 Operation Frequency	f _{OSC_1345}		1800	2000	2200	kHz
CH2, 7 Operation Frequency	f _{OSC_27}	CH7 in Step-Up mode	900	1000	1100	kHz
CH1 LV Sync Step-Up					•	
Output Voltage Accuracy at PVD1		Target voltage defined at A4.VOUT1 [3:0]	-1.5		1.5	%
Minimum On Time for PSM				100		ns
Soft-Start Time		PVD1 = 0 to 5V		4		ms
Maximum Duty Cycle (Step-Up)		PVD1 < Target defined in A4.VOUT1 [3:0]	80	83	86	%
On Desistance of MOCEET	R _{DS(ON)_P}	P-MOSFET, PVD1 = 3.3V		200		mΩ
n Resistance of MOSFET	R _{DS(ON)_N}	N-MOSFET, PVD1 = 3.3V		150	250	mΩ
Current Limitation (Step-Up)	I _{LIM_1}		2.2	3	4	Α
Over Voltage Protection at PVD1			5.82	6	6.18	V
Under Voltage Protection -1 at PVD1				SYS - 0.8		V
Under Voltage Protection -2 at PVD1		Target Voltage is defined in A4.VOUT1 [3:0]	ı	Target x 0.5		V
Over Load Protection at PVD1		Target Voltage is defined in A4.VOUT1 [3:0]		Target – 0.6		V
Off Discharge Current at PVD1		PVD1 = 5V, SYS = 3.3V		20		mA
Discharge Finishing Threshold at PVD1			ı	0.6		V
CH2 LV Sync Step-Up/Down						
Feedback Regulation Voltage at FB2		A4.FB2 [2:0] = 3'b100	0.788	0.8	0.812	V
Soft-Start Time		FB2 = 0 to 0.8V		4		ms
Maximum Duty Cycle		LX2B		55		%
maximum buty Cyolo		LX2A			100	%
On Resistance of MOSFET	R _{DS(ON)_2A}	LX2A – GND, N-MOSFET PVD2 = 3.3V	1	200	300	mΩ
On Residence of Wood E1	1, 109(ON)_2A	PVD2 – LX2A, P-MOSFET PVD2 = 3.3V		150	250	mΩ

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Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
On Resistance of MOSFET	Proyent on	VO2–LX2B, P-MOSFET, VO2 = 3.3V		200	300	mΩ
Off Resistance of MOSFET	R _{DS(ON)_2B}	N-MOSFET VO2 = 3.3V		150	250	mΩ
Current Limitation	I _{LIM_2}	Both P-MOSFET (PVD2 – LX2A) and N-MOSFET (LX2B – GND)	2	2.5	3	Α
Over Voltage Protection at VO2			5.82	6	6.18	V
Under Voltage Protection at FB2		Target voltage is the chosen one in A4.FB2 [2:0]		0.4		V
Over Load Protection at FB2				Target - 0.1		V
Off Discharge Current at VO2		VO2 = 3.3V, SYS = 3.3V		20		mA
Discharge Finishing Threshold at VO2				0.1		V
CH3 LV Sync Step-Down						
Feedback Regulation Voltage at FB3		A5.FB3 [2:0] = 3'b100	0.788	0.8	0.812	V
Minimum On Time for PSM				50		ns
Maximum Duty Cycle		FB3 = 0.75V			100	%
Soft-Start Time		FB3 = 0 to 0.8V		4		ms
On Desistance of MOCEST	R _{DS(ON)_P}	P-MOSFET, PVD3 = 3.3V		200	300	mΩ
On Resistance of MOSFET	R _{DS(ON)_N}	N-MOSFET, PVD3 = 3.3V		150	250	mΩ
Current Limitation	I _{LIM_3}		1.3	1.8	2.4	Α
Under Voltage Protection at FB3			0.35	0.4	0.45	V
Over Load Protection at FB3		Target voltage is the chosen one in A5.FB3 [2:0]		Target - 0.1		V
Off Discharge Current at LX3		LX3 = 1V, SYS = 3.3V		20		mA
Discharge Finishing Threshold at FB3				0.1		V
CH4 LV Sync Step-Down						
Feedback Regulation Voltage at FB4		A5.FB4 [2:0] = 3'b100	0.788	0.8	0.812	V
Minimum On Time for PSM				50		ns
Maximum Duty Cycle		FB4 = 0.75V			100	%
Soft-Start Time		FB4 = 0 to 0.8V		4		ms
On Designation of MOSEFT	R _{DS(ON)_P}	P-MOSFET, PVD4 = 3.3V		300	400	mΩ
On Resistance of MOSFET	R _{DS(ON)_N}	N-MOSFET, PVD4 = 3.3V		200	300	mΩ
Current Limitation	I _{LIM_4}		1.3	1.8	2.4	Α
Under Voltage Protection at FB4			0.35	0.4	0.45	V
Over Load Protection at FB4		Target voltage is the chosen one in A5.FB4 [2:0]		Target - 0.1		V
Off Discharge Current at LX4		LX4 = 1V, SYS = 3.3V		20	-	mA
Discharge Finishing Threshold at FB4				0.1		V



Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
CH5 LV Sync Step-Down	•		•			
Output Voltage Accuracy at		Target voltage defined at A6.VOUT5 [3:0] = 4'b1000 to 4'b1111	-1.5		1.5	%
VO5		Target voltage defined at A6.VOUT5 [3:0] = 4'b0001 to 4'b0111	-2		2	%
Feedback Regulation Voltage at FB5		A6.VOUT5 [3:0] = 4'b0000	0.788	0.8	0.812	V
Maximum Duty Cycle					100	%
Soft-Start Time		VO5 = 0V to Target		4		ms
On Posistance of MOSEET	R _{DS(ON)_P}	P-MOSFET, PVD5 = 3.3V		400	550	mΩ
On Resistance of MOSFET	R _{DS(ON)_N}	N-MOSFET, PVD5 = 3.3V		250	400	$m\Omega$
Current Limitation	I _{LIM_5}		1	1.5	2	Α
Under Voltage Protection at VO5				Target x 0.5	ı	
		Target voltage is the chosen one in A6.VOUT5 [3:0] = 0000 (FB5 = 0.8)		Target - 0.1	1	V
Over Load Protection at VO5		Target voltage is the chosen one in A6.VOUT5 [3:0] = 0001 to 0111		Target - 0.167		V
		Target voltage is the chosen one in A6.VOUT5 [3:0] = 0111 to 1111		Target - 0.25	1	
Off Discharge Current at VO5		VO5 = 1.8V, SYS = 3.3V		30	-	mA
Discharge Finishing Threshold at VO5				0.1	-	V
CH6 LDO						
Input Voltage Range (PVD6)			1.5		5.5	V
Quiescent Current into PVD6		PVD6 = 3.3V, I _{OUT} = 0mA			75	μΑ
Regulation Voltage Accuracy		A6.VOUT6 [3:0] = 4'b1000 to 4'b1111	-1.5		1.5	%
at VO6		A6.VOUT6 [3:0] = 4'b0000 to 4'b0111	-2		2	%
Drop Out Voltage (PVD6-VO6)		I _{OUT} = 300mA, VO6 = 1.3V			0.15	٧
PSRR+		I _{OUT} = 10mA, PVD6 = 3.3V at 1kHz		-60		dB
Max Output Current (Current Limit)		PVD6 = 1.5V, VO6 = 1.3V	300	450	600	mA
Off Discharge Current at VO6		SYS = 3.3V			10	mA
CH7 WLED Driver						
Feedback Regulation Voltage at FB7 (Both Step-Up and Current)		A2.EN7_DIM7 [4:0] = 5'b11111	0.237	0.25	0.263	V
Minimum On Time for PSM (Step-Up)				300	-	ns
Maximum Duty Cycle (Step-Up mode)		FB7 = 0.15V	91	93	97	%

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Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
On Resistance of MOSFET	R _{DS(ON)_P}	P-MOSFET, PVD7 = 10V		2	3	Ω
On Resistance of MOSFET	R _{DS(ON)_N}	N-MOSFET, SYS = 3.3V		0.9	1.1	Ω
Current Limitation (Step-Up mode)		N-MOSFET, SYS = 3.3V	0.6	0.8	1	Α
Over Voltage Protection at PVD7		A0.OVP7 = 0	15	16	17	V
(Step-Up mode)		A0.OVP7 = 1	24	25	26	V
Off Discharge Current at PVD7 (Step-Up mode)		PVD7 = 10V, SYS = 3.3V		20		mA
Discharge Finishing Threshold at PVD7		(Step-Up Mode)		SYS - 0.4		V
CH8 LDO						
Input Voltage Range (PVD8)			1.5		5.5	V
Quiescent Current into PVD8	I _{Q_PVD8}	PVD8 = 3.3V, I _{OUT} = 0mA			75	μΑ
Regulation Voltage Accuracy at		A3.VOUT8 [3:0] = 4'b1000 to 4'b1111	-1.5		1.5	%
VO8		A3.VOUT8 [3:0] = 4'b0000 to 4'b0111	-2		2	%
Drop Out Voltage (PVD8-VO8)		I _{OUT} = 300mA, VO8 = 2.5V			0.2	V
PSRR+		I _{OUT} = 10mA, PVD8 = 3.3V at 1kHz		-60		dB
Max Output Current (Current Limit)		PVD8 = 3V, VO8 = 2.5V	300	450	600	mA
Off Discharge Current at VO8		SYS = 3.3V			10	mΑ
CH9 RTC LDO						
Standby Quiescent Current		BAT = 4.2V		3	6	μΑ
Lockout Current into VRTC	I _{LO-VRTC}	EN = L, and PMU off, BAT = 0V, VRTC = 3.05V, SYS = 0V			1	μΑ
Regulation Voltage at VRTC		I _{OUT} = 0mA	3	3.05	3.1	V
Max Output Current (Current Limit)		BAT = 4.2V	60	130	200	mA
		I _{OUT} = 50mA			1000	mV
Dropout Voltage at (BAT-VRTC)		I _{OUT} = 10mA			150	mV
		$I_{OUT} = 3mA$			60	mV
Wake Up Detector						
WAKE Impulse High Duration	tWAKEUP	VIN or BAT plug in, VRTC = 3.05V	60	90	120	ms
WAKE UP High Level	V _{WAKE_H}	Source Current 0.5mA, VRTC = 3.05V		VRTC - 0.3V	VRTC	V
WAKE UP Low Level	V _{WAKE_L}	Sink Current 0.5mA, VRTC = 3.05V	0	0.3		V
WAKE UP Rising Time	twake_r	C _{LOAD} 100pF at WAKE pin, 10% to 90% of VRTC, VRTC = 3.05V			1	μS
BAT Wake Up Threshold Voltage		VRTC = 3.05V	3	3.1	3.2	V
BAT Wake Up Threshold Hysteresis Gap		VRTC = 3.05V		-0.28		V



Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
VIN Wake Up Threshold Voltage		VRTC = 3.05V	3.55	3.75	4	V
VIN Wake Up Threshold Gap		VRTC = 3.05V		-0.24		V
Control						
EN Input High Level Threshold			1.3			V
EN Input Low Level Threshold					0.4	V
EN Pull Down Current				1	3	μА
SEQ Pull High Threshold for Power Sequence #0			0.2			V
SEQ Pull Down Resistance for Power Sequence #1		BAT = SYS = 2.7V	25	40	64	kΩ
SEQ Pull Down Resistance for Power Sequence #2		BAT = SYS = 2.7V	6.25	10	16	kΩ
SEQ Pull Down Resistance for Power Sequence #3		BAT = SYS = 2.7V	1.56	2.5	4	kΩ
SEQ Pull Down Resistance for Power Sequence #4		BAT = SYS = 2.7V		0.63	1	kΩ
SEQ Pull Low Threshold for Power Sequence #4					0.2	V
SEQ Pull Down Resistance for Power Sequence #5		BAT = SYS = 2.7V	100	160		kΩ
Power Sequence Time Gap		From previous channel starting to next channel starting	9	10	11	ms
Protection	•	•	•	•	•	•
Protection Fault Delay				100		ms
Thermal Shutdown	T _{SD}		125	155		°C
Thermal Shutdown Hysteresis	ΔT_{SD}			20		°C



Charger Unit:

($V_{IN} = 5V$, $V_{BAT} = 4V$, $T_A = 25$ °C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Supply Input						
VIN Under Voltage Lockout Threshold	V _{UVLO}	V _{IN} = 0V to 4.5V	3.1	3.3	3.5	V
VIN Under Voltage Lockout Hysteresis	Δνυνιο	V _{IN} = 4.5V to 0V		240		mV
VIN Supply Current	lavianiv	$I_{SYS} = I_{BAT} = 0$ mA, A7. $\overline{ENCH} = 0$ ($V_{BAT} > V_{REGx}$)		1	2	mA
VIIV Supply Current	ISUPPLY	$I_{SYS} = I_{BAT} = 0mA, A7.\overline{ENCH} = 1$ (V _{BAT} > V _{REGx})	-	0.8	1.5	mA
VIN Suspend Current	lusus	V _{IN} = 5V, A7.USUS = 1	ŀ	195	300	μΑ
VIN-BAT VOS Rising	V _{OS_H}			200	300	mV
VIN-BAT VOS Falling	V _{OS_L}		10	50		mV
Voltage Regulation						
System Regulation Voltage	V _{SYS}	I _{SYS} = 800mA	4.9	5	5.1	V
Battery Regulation Voltage	V _{REG1}	0 to 85°C, Loading = 20mA, When A9. VSETH = 1 and A9.VSETC = 1	4.16	4.2	4.23	V
Battery Regulation Voltage	V _{REG2}	0 to 85°C, Loading = 20mA, When A9. VSETH = 0 and A9. VSETC = 0	4.01	4.05	4.08	٧
APPM Regulation Voltage	V_{APPM}		4.05	4.15	4.25	V
DPM Regulation Voltage	V_{DPM}		4.25	4.35	4.45	V
VIN to VSYS MOSFET Ron	R _{DS(ON)}	I _{VIN} = 1000mA		0.2	0.35	Ω
BAT to VSYS MOSFET Ron	R _{DS(ON)}	V _{BAT} = 4.2V, I _{SYS} = 1A		0.05	0.1	Ω
Re-Charge Threshold	ΔV_{REGCHG}	Battery Regulation - Recharge level	60	100	140	mV
Current Regulation						
Charge Current Setting Range	I _{CHG}		100		1200	mA
Charge Current Accuracy1	I _{CHG1}	V _{BAT} = 4V, A8.ISETA [3 : 0] = 4'b0101	570	600	630	mA
Charge Current Accuracy2	I _{CHG2}	VBAT = 3.8V, A8.ISETA [3 : 0] = 4'b0010	285	300	315	mA
		A7.ISETL = 1, A7.ISETU = 1 (1.5A Mode)	1.5	1.8	2.1	Α
VIN Current Limit	Luka vaki	A7.ISETL = 1, A7.ISETU = 0 (1A Mode)	0.85	0.925	1.0	Α
VIIV GUITORE EIRIRE	ILIM_VIN	A7.ISETL = 0, A7.ISETU = 1 (500mA mode)	450	475	500	mA
		A7.ISETL = 0, A7.ISETU = 0 (100mA Mode)	80	90	100	mA
Pre-Charge	1	,		1		
BAT Pre-Charge Threshold	V _{PRECH}	BAT Falling	2.7	2.8	2.9	V
BAT Pre-Charge Threshold Hysteresis	ΔV_{PRECH}			200		mV
Pre-Charge Current	I _{CHG_PRE}	V _{BAT} = 2V	5	10	15	%



Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Charge Termination Detection	n					
Termination Current Ratio to Fast Charge (Except USB 100 Mode)	I _{TERM}	A7.ISETL = 0, A7.ISETU = 1 Or A7.ISETL = 1, A7.ISETU = X	5	10	15	%
Termination Current Ratio to Fast Charge (USB100 Mode)	I _{TERM2}	A7.ISETL = 0, A7.ISETU = 0		3.3		%
Login Input/Output						
CHG Pull Down Voltage	V _{CHG}	I _{CHG} = 5mA		200		mV
CHG2 Pull Down Voltage	V _{CHG2}	I _{CHG2} = 5mA		200		mV
INT Pull Down Voltage	V _{INT}	I _{INT} = 5mA		200		mV
Protection						
Thermal Regulation Point	T _{REG}			125		°C
Thermal Shutdown Temperature	T _{SD}			155		°C
Thermal Shutdown Hysteresis	ΔT _{SD}			20		°C
Over Voltage Protection	V _{OVP}	V _{IN} Rising	6.25	6.5	6.75	V
Over Voltage Protection Hysteresis	ΔV _{OVP}	$V_{IN} = 7V \text{ to } 5V, VOVP - \Delta VOVP$		100		mV
Output Short Circuit Detection Threshold	V _{SHORT}	VBAT – VSYS		300		mV
Battery Installation Detection Threshold at TS		EN = H (PMU enabled), report at A10. NoBAT bit		90		% of VP
Time						
Input Over Voltage Blanking Time	tovp			50		μS
Pre-Charge to Fast-Charge Deglitch Time	t _{PF}			25		ms
Fast-Charge to Pre-Charge Deglitch Time	t _{FP}			25		ms
Termination Deglitch Time	t _{TERMI}			25		ms
Recharge Deglitch Time	t _{RECHG}			100		ms
Input Power Loss to SYS LDO Turn-Off Delay Time	t _{NO_IN}			25		ms
Pack Temperature Fault Detection Deglitch Time	t _{TS}			25		ms
Short Circuit Deglitch Time	t _{SHORT}			250		μS
Short Circuit Recovery Time	t _{SHORT-R}			64		ms
Other						
VP Regulation Voltage	V_{VP}	V _{SYS} = 4.2V	3.234	3.3	3.366	V
VP Load Regulation	V_{VP}	VP source out 2mA			-0.1	V



Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
VP Under Voltage Lockout Threshold		Falling Threshold		0.8		V
TS Battery Detect Threshold	V _{TS}		2.75	2.85	2.95	V
NTC Temperature Sense						
Low Temperature Trip Point	V _{TOO_COLD}	NTC = 100kΩ	73	74	75	% of VP
(0°C)	V _{TOO_} COLD	NTC = $10k\Omega$	59	60	61	% of VP
Low Temperature Trip Point	V _{COLD}	NTC = 100kΩ	63	64	65	% of VP
(10°C) for JEITA	V _{COLD}	NTC = $10k\Omega$	51	52	53	% of VP
High Temperature Trip Point	V _{HOT}	NTC = 100kΩ	34	35	36	% of VP
(45°C) for JEITA	V _{HOT}	NTC = $10k\Omega$	31	32	33	% of VP
High Temperature Trip Point	V _{TOO_HOT}	NTC = $100k\Omega$, A8.TSHT [1:0] = 2'b00	27	28	29	% of VP
(60°C)	V _{ТОО_НОТ}	NTC = $10k\Omega$, A8.TSHT [1:0] = 2'b00	27	28	29	% of VP
High Temperature Trip Point Hysteresis for JEITA				1		% of VP
Charger Detection						
VDP_SRC Voltage	VDP_SRC	With IDAT_SRC = 0 to 200μA	0.5		0.7	V
VDAT_REF Voltage	VDAT_REF		0.25		0.4	V
VLGC Voltage	VLGC		0.8		2.0	V
IDP_SRC Current	IDP_SRC		6.6		11	μΑ
D+ and D- Sink Current	ICD+_SINK ICDSINK		50		150	μА
D- Pull down Resistor	RDDWN		14.25		24.8	kΩ
Data Contact Detect Debounce	TDCD_DBNC		20	30	40	ms
DCD Time OUT	TDCD_TO		300		900	ms
VDAT_SRC ON Time	TDP_SRC_ON		100		200	ms



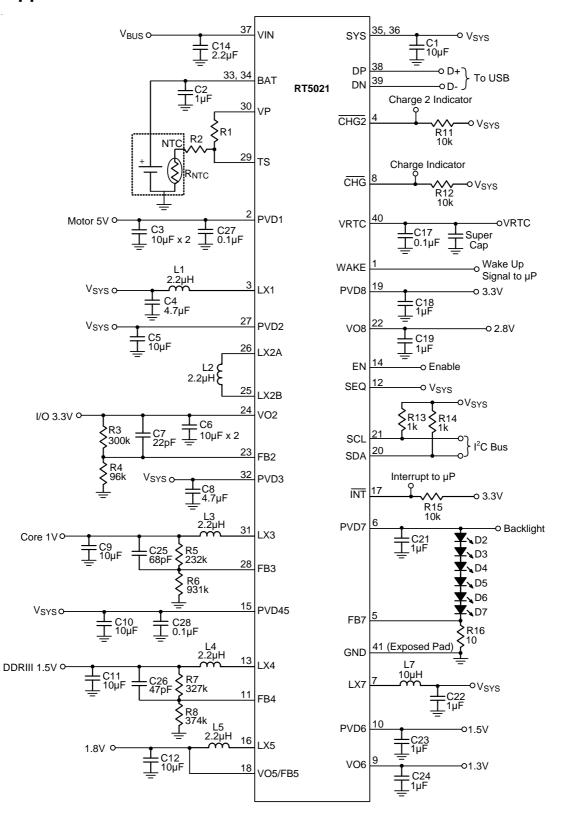
($V_{SYS} = 3.3V$, $T_A = 25$ °C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
r ² C						
SDA, SCLK Input High Level Threshold			1.4			V
SDA, SCLK Input Low Level Threshold			-		0.6	V
SCLK Clock Rate	f _{SCL}				400	kHz
Hold Time (repeated) START Condition. After this period, the first clock pulse is generated.	t _{HD,STA}		0.6			μs
LOW Period of the SCL Clock	t _{LOW}		1.3			μS
HIGH Period of the SCL Clock	thigh		0.6			μS
Set-Up Time for a Repeated START Condition	tsu,sta		0.6			μS
Data Hold Time	t _{HD,DAT}		0		0.9	μS
Data Set-Up Time	t _{SU,DAT}		100		-	ns
Set-Up Time for STOP Condition	t _{SU,STO}		0.6			μS
Bus Free Time between a STOP and START condition	t _{BUF}		1.3			μS
Rise time of both SDA and SCL signals	t _R		20		300	ns
Fall Time of Both SDA and SCL Signals	t _F		20		300	ns
SDA and SCL Output Low Sink Current	I _{OL}	SDA or SCL voltage = 0.4V	2			mA

- Note 1. Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
- Note 2. θ_{JA} is measured at $T_A = 25^{\circ}C$ on a high effective thermal conductivity four-layer test board per JEDEC 51-7. θ_{JC} is measured at the exposed pad of the package.
- Note 3. Devices are ESD sensitive. Handling precaution is recommended.
- Note 4. The device is not guaranteed to function outside its operating conditions.



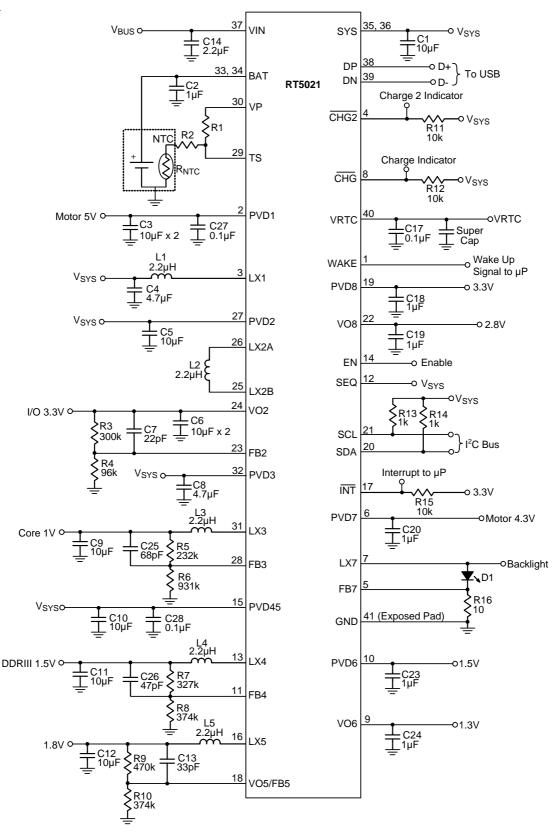
Typical Application Circuit



Note: To make CH1 stable, C27 must be close to PVD1. To make CH4 and CH5 stable, C28 must be close to PVD45.

Figure 1. Typical Application Circuit for DSC with 6-LED Backlight





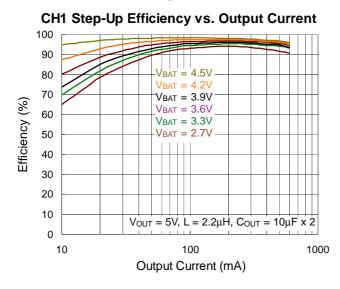
Note: To make CH1 stable, C27 must be close to PVD1. To make CH4 and CH5 stable, C28 must be close to PVD45.

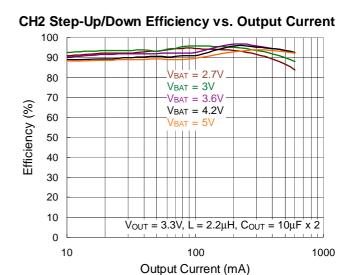
Figure 2. Typical Application Circuit for DSC with One LED Backlight

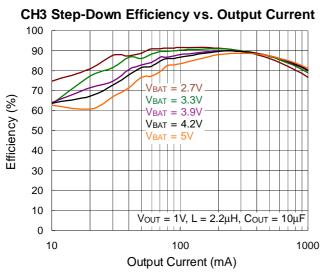


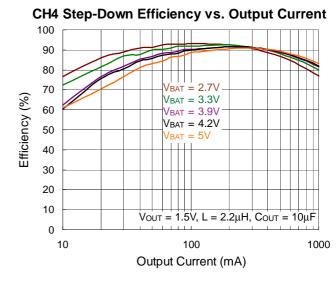
Typical Operating Characteristics

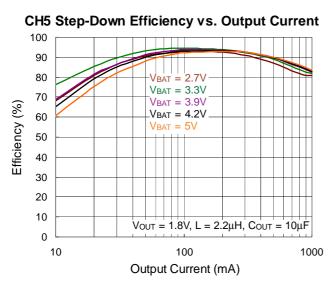
 $V_{IN} = 5V$, unless otherwise specified.

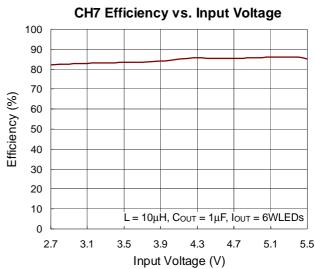




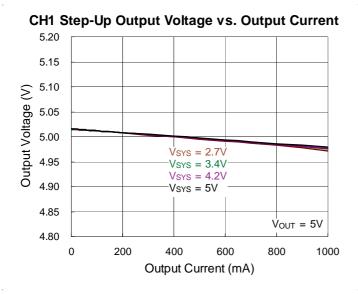


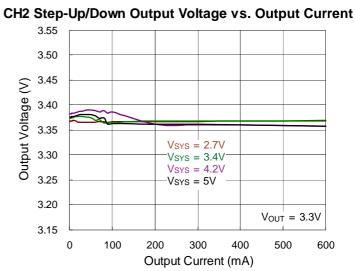


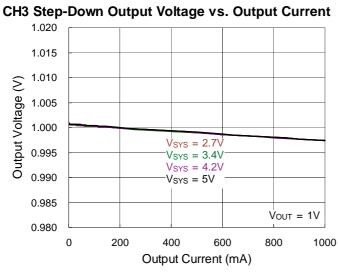


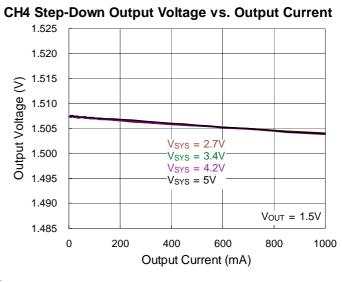


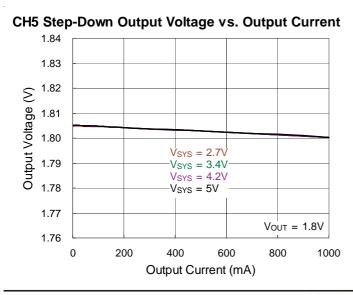


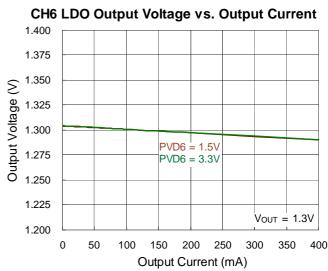






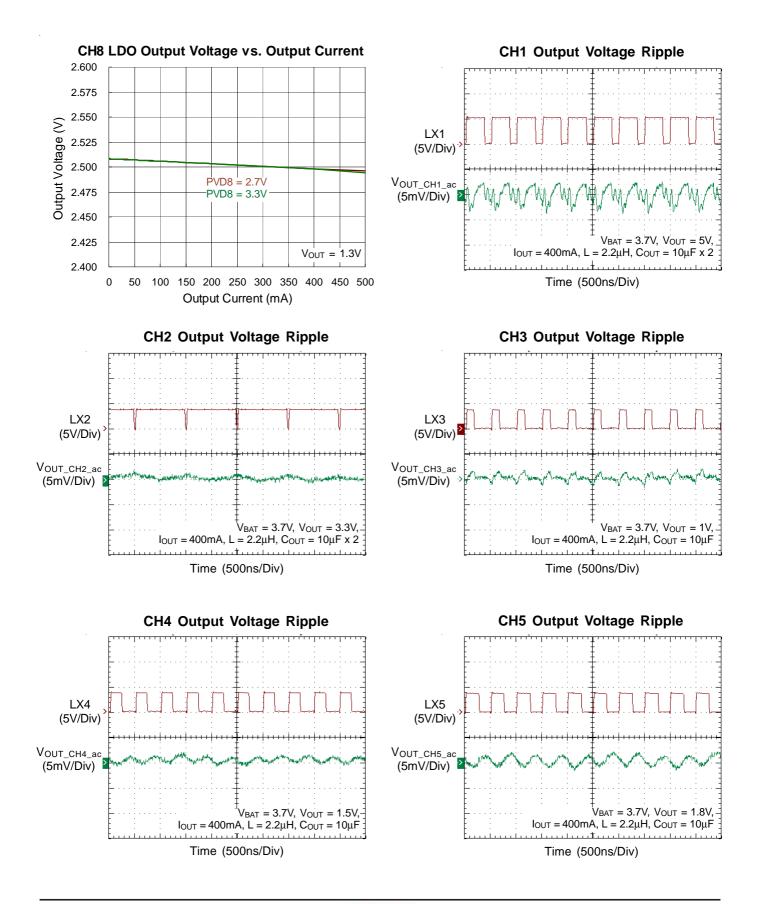




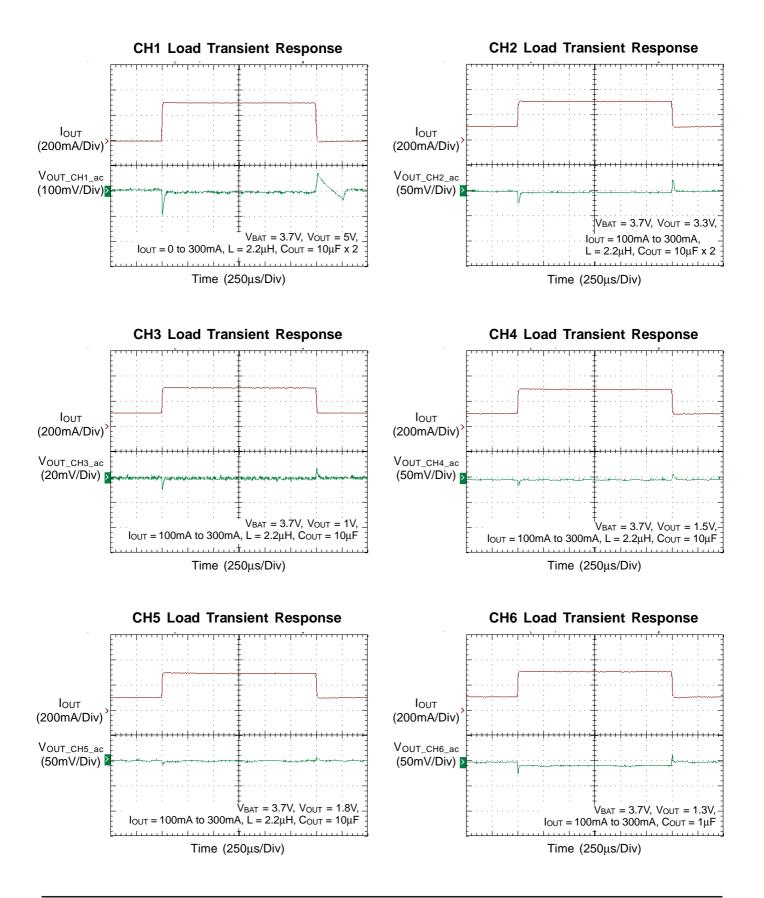


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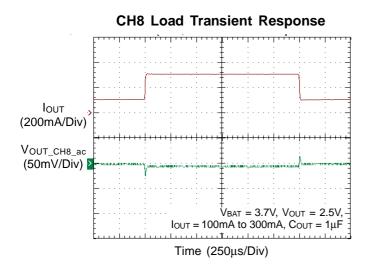


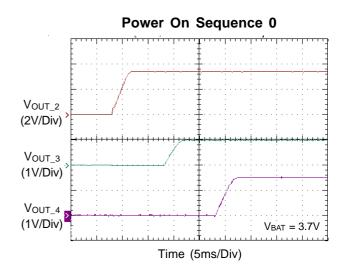


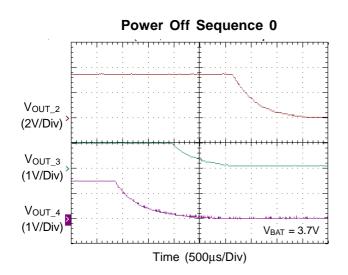


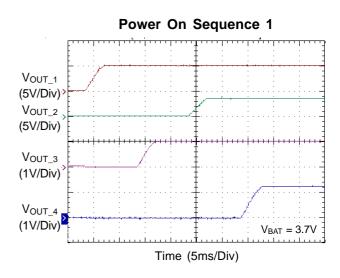


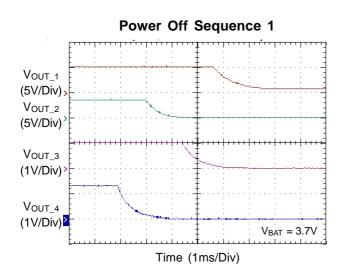


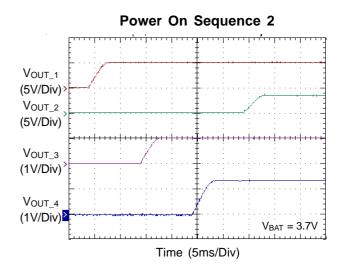




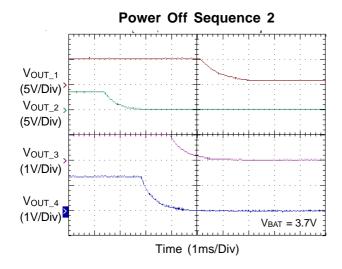


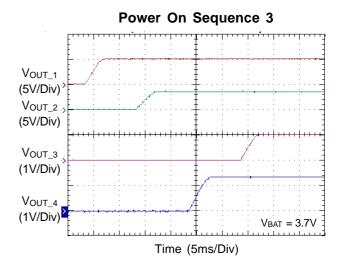


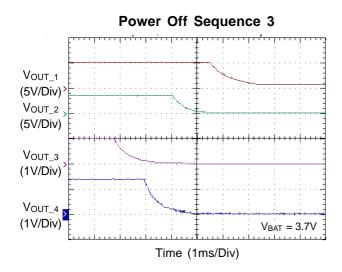


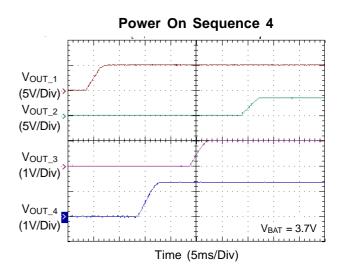


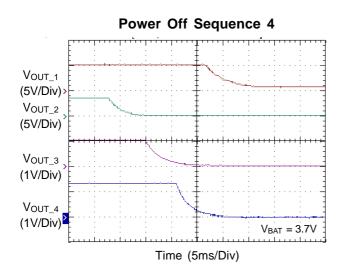


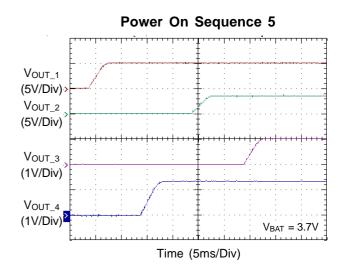




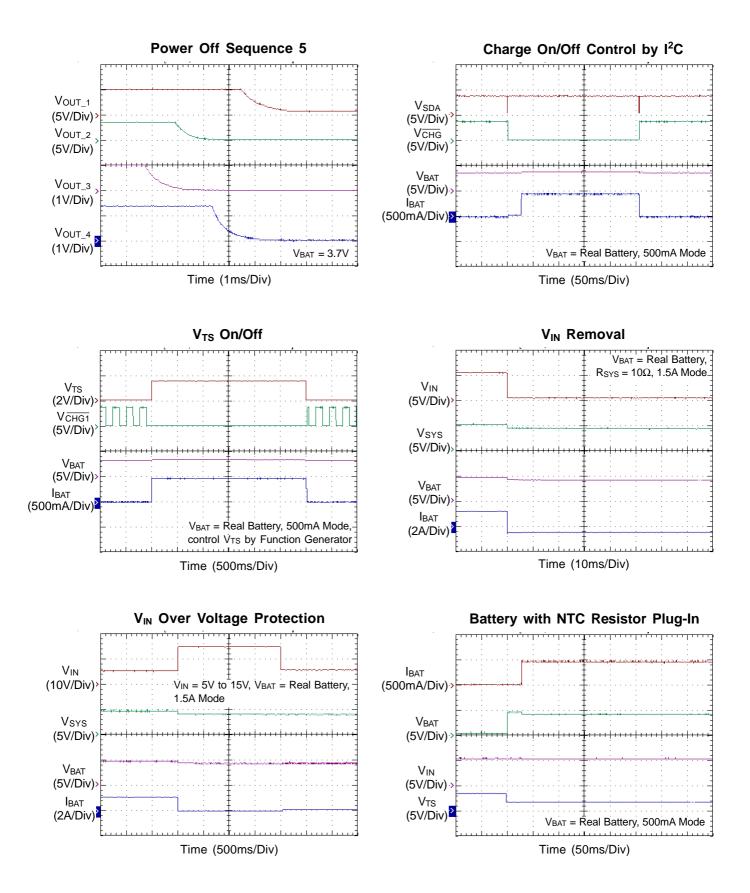




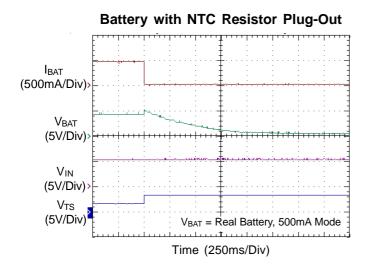


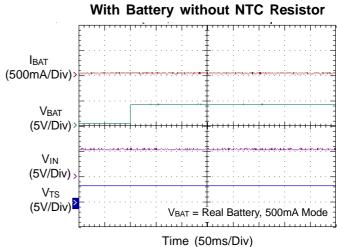


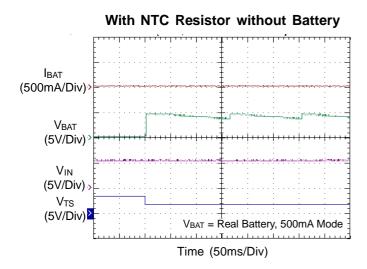


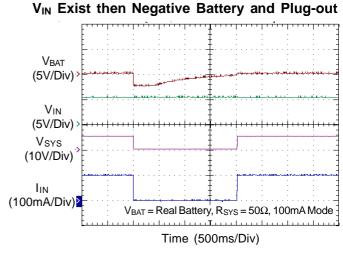


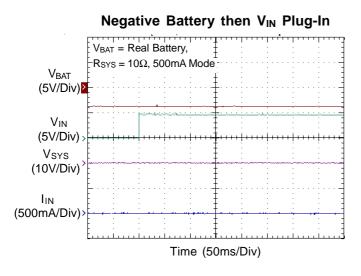


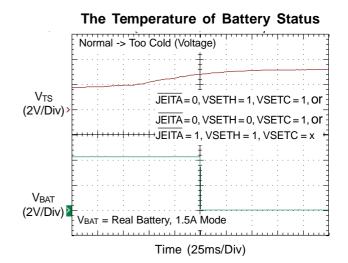






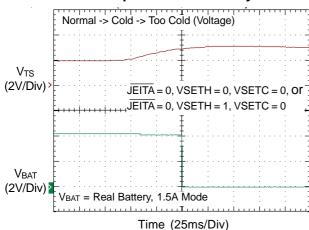




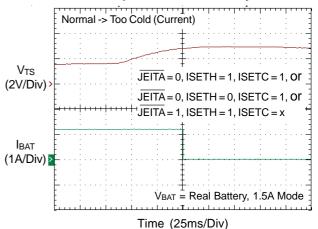




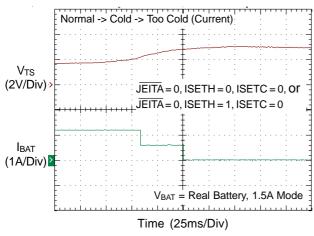
The Temperature of Battery Status



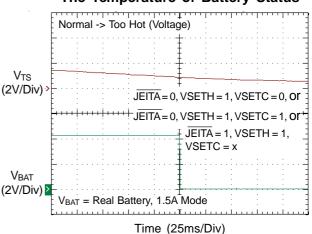
The Temperature of Battery Status



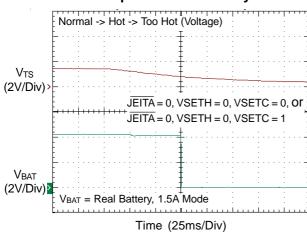
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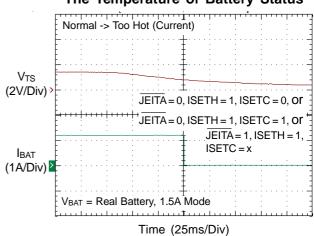
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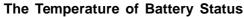
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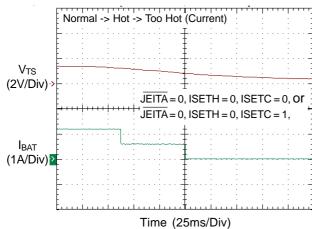


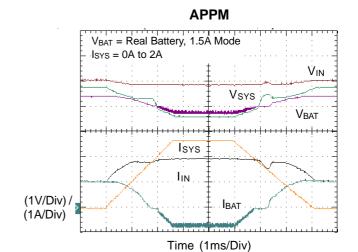
The Temperature of Battery Status



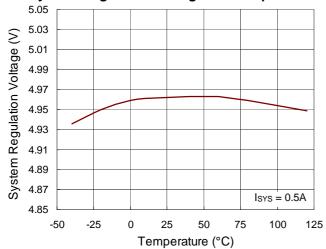




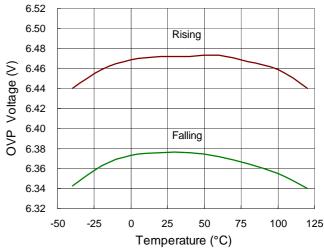




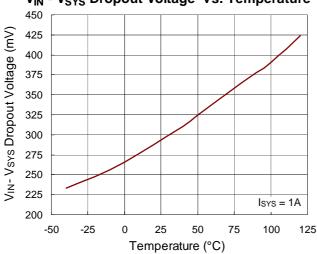
System Regulation Voltage vs. Temperature



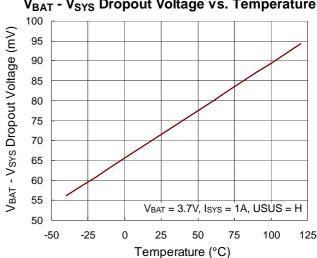




V_{IN} - V_{SYS} Dropout Voltage vs. Temperature



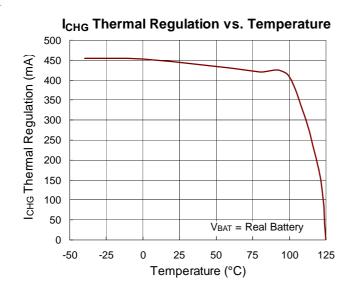
V_{BAT} - V_{SYS} Dropout Voltage vs. Temperature

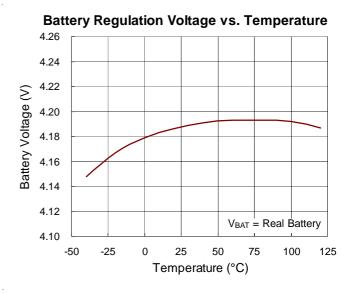


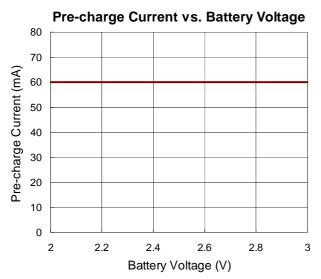
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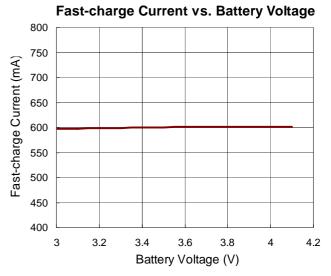
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Application Information

Power Converter Unit

The RT5021 is an integrated power solution for digital still cameras and other small handheld devices. It includes six DC-DC converters, a WLED driver, two low output LDO, a RTC LDO, and a fully integrated single-cell Li-ion battery charger that is ideal for portable applications.

CH1: Synchronous Step-Up DC-DC Converter

The synchronous step-up DC-DC converter can be operated in either PFM or Sync-PWM mode by setting I²C. It includes internal power MOSFETs, compensation network and feedback resistors. The P-MOSFET can be controlled to disconnect output loading. It is suitable for providing power to the motor. The output voltage of CH1 can be adjusted by the I²C interface in the range of 3.6V to 5.5V.

	CH1 regulation voltage can be selected by I ² C interface. The default voltage is 5V.							
	Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage
VOUT1 [3:0]	0000	3.6V	0001	3.7V	0010	3.8V	0011	3.9V
V O O 1 1 [0.0]	0100	4V	0101	4.5V	0110	4.6V	0111	4.7V
	1000	4.8V	1001	4.9V	1010	5V	1011	5.1V
	1100	5.2V	1101	5.3V	1110	5.4V	1111	5.5V

CH2: Synchronous Step-Up/Down (Buck-Boost) DC-DC Converter

The synchronous step-up/down (Buck-Boost) DC-DC converter can be operated in either PFM or Sync-PWM mode by setting I²C. It includes internal power MOSFETs, compensation network and feedback resistors. This channel supplies the power for I/O. The FB voltage of CH2 can be adjusted by the I²C interface in the range of 0.72V to 0.86V.

	FB2 regulati	FB2 regulation voltage can be selected by I ² C interface. The default voltage is 0.8V.							
	Code	VREF	If Target = 1.8V	If Target = 1V	If Target = 3.3V				
	000	0.72V	1.62V	0.9V	2.97V				
	001	0.74V	1.665V	0.925V	3.0525V				
FB2 [2:0]	010	0.76V	1.71V	0.95V	3.135V				
1 52 [2.0]	011	0.78V	1.755V	0.975V	3.2175V				
	100	0.8V	1.8V	1V	3.3V				
	101	0.82V	1.845V	1.025V	3.3825V				
	110	0.84V	1.89V	1.05V	3.465V				
	111	0.86V	1.935V	1.075V	3.5475V				



CH3 to CH4: Step-Down Synchronous DC/ DC Converter

The step-down synchronous DC/DC converters include internal power MOSFETs and compensation network. It support PFM or Sync-PWM mode by setting I²C. These channels supply the power for core and DRAM. They can be operated at 100% maximum duty cycle to extend battery operating voltage range. When the input voltage is close to the output voltage, the converter enters low dropout mode with low output ripple. The FB voltage of CH3 and CH4 can be adjusted by the I²C interface in the range of 0.72V to 0.86V.

	FB3 regulation voltage can be selected by I ² C interface. The default voltage is 0.8V.						
	Code	VREF	If Target = 1.8V	If Target = 1V	If Target = 3.3V		
	000	0.72V	1.62V	0.9V	2.97V		
	001	0.74V	1.665V	0.925V	3.0525V		
FB3 [2:0]	010	0.76V	1.71V	0.95V	3.135V		
1 03 [2.0]	011	0.78V	1.755V	0.975V	3.2175V		
	100	V8.0	1.8V	1V	3.3V		
	101	0.82V	1.845V	1.025V	3.3825V		
	110	0.84V	1.89V	1.05V	3.465V		
	111	0.86V	1.935V	1.075V	3.5475V		

	FB4 regulation voltage can be selected by I ² C interface. The default voltage is 0.8V.							
	Code	VREF	If Target = 1.8V	If Target = 1V	If Target = 3.3V			
	000	0.72V	1.62V	0.9V	2.97V			
	001	0.74V	1.665V	0.925V	3.0525V			
FB4 [2:0]	010	0.76V	1.71V	0.95V	3.135V			
1 64 [2.0]	011	0.78V	1.755V	0.975V	3.2175V			
	100	0.8V	1.8V	1V	3.3V			
	101	0.82V	1.845V	1.025V	3.3825V			
	110	0.84V	1.89V	1.05V	3.465V			
	111	0.86V	1.935V	1.075V	3.5475V			

If CH3/CH4 input voltage (PVD3/PVD45) is higher than 4.2V and the output voltage is lower than 1.5V, a feed forward capacitor can be added improve the transient response.

The capacitance can be estimated by the following equation.

$$C_{ff} = \frac{15.5 \times 10^{-6}}{R1}$$

For example, when R1 is $470k\Omega$, the available feed-forward capacitor is 33pF.



CH5: Step-Down Synchronous DC/ DC Converter

The step-down synchronous DC/DC converter includes internal power MOSFETs and compensation network. They can be operated at 100% maximum duty cycle to extend battery operating voltage range. When the input voltage is close to the output voltage, the converter enters low dropout mode with low output ripple. The output voltage can be selected as the following list or set by external feedback network.

	CH5 regulation voltage can be selected by I ² C interface. The default voltage is 1.8V.							
	Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage
	0000	REF	0001	1.1V	0010	1.2V	0011	1.3V
VOUT5 [3:0]	0100	1.4V	0101	1.5V	0110	1.6V	0111	1.7V
1 00 10 [0.0]	1000	1.8V	1001	2V	1010	2.2V	1011	2.3V
	1100	2.5V	1101	2.6V	1110	2.7V	1111	2.8V
		OUT5 [3:0] : target is 0.8	,	EF) means	using exte	rnal feedba	ick networl	k and FB5

CH6: Low Voltage LDO

CH6 is a low voltage LDO and its output voltage is controlled by I²C interface. This supplies the multiple purpose power. The output voltage of CH6 can be adjusted by the I²C interface in the range of 1.1V to 3.3V.

	² C interfac	e. The defa	ult voltage	is 1.3V.				
	Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage
VOUT6 [3:0]	0000	Switch	0001	1.1V	0010	1.2V	0011	1.3V
VO016 [3.0]	0100	1.4V	0101	1.5V	0110	1.6V	0111	1.7V
	1000	1.8V	1001	2V	1010	2.2V	1011	2.5V
	1100	2.8V	1101	3.1V	1110	3.2V	1111	3.3V

CH7: Current Source/Step-Up WLED Driver

The WLED drivers operating in either current source mode or synchronous step-up mode include internal power MOSFET and compensation network. The operation mode is determined by setting I²C. The P-MOSFET in step-up mode can be controlled to disconnect the output loading.

When CH7 works in current source mode, it likes a LDO and regulates the current by FB7 voltage. The LED current is defined by the FB7 voltage as well as the external resistor between FB7 and GND. The FB7 regulation voltage can be set in 31 steps from 8mV to 250mV. If CH7 works in synchronous step-up mode, it can support an output voltage up to 15V or 21V controlled by I²C interface. The LED current is also set via an external resistor and FB7 regulation voltage.

The WLED current can be set by the following equation:

ILED (mA) = $[250 \text{mV} / \text{R} (\Omega)] \times \text{EN7_DIM7} [4:0] / 31$

Where R is the current sense resistor from FB7 to GND and EN7_DIM7 [4:0] / 31 ratio refers to the I²C control register file.



CH8: Low Voltage LDO

CH8 is a low voltage LDO and its output voltage is controlled by I²C interface. It supplies for multiple purpose power. The output voltage of CH8 can be adjusted by the I²C interface in the range of 1.1V to 3.3V.

	CH8 regulation voltage can be selected by I ² C interface. The default voltage is 2.8							
	Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage
VOUT8 [3:0]	0000	Switch	0001	1.1V	0010	1.2V	0011	1.3V
V 0 0 1 0 [0.0]	0100	1.4V	0101	1.5V	0110	1.6V	0111	1.7V
	1000	1.8V	1001	2V	1010	2.2V	1011	2.5V
	1100	2.8V	1101	3.1V	1110	3.2V	1111	3.3V

RTC_LDO: Accuracy 3.05V LDO Output.

The RT5021 provides a 3.05V output LDO for real-time clock. The LDO features low quiescent current (3μA), reverse leakage prevention from output node and high output voltage accuracy. This LDO is always on, even when the system is shut down. For better stability, it is recommended to connect a 0.1µF capacitor to the RTCPWR pin. The RTC LDO includes pass transistor body diode control to avoid the RTCPWR node from back-charging into the input node VDDI.

Switching Frequency

The converters of CH1, CH3, CH4 and CH5 operate in PWM mode with 2MHz switching frequency. The converters of CH2 and CH7 operates in PWM mode with 1MHz switching frequency.

Power On/Off Sequence and deglitch function for CH1 to CH4

SEQ pull down resistance R_{SEQ} Defines power on/off sequence.

SEQ#	R _{SEQ} (I Range							
SEQ#	Min	Тур	Max					
SEQ #0	Sho	Short to Power (>0.2V)						
SEQ #1	25	40	64					
SEQ #2	6.25	10	16					
SEQ #3	1.56	2.5	4					
SEQ #4	-	0.63	1					
SEQ #5	100	160						

SEQ # 0 : CH2 CH3 CH4 (CH1 is decided by register A4 bit3.)

SEQ #1: CH1 \rightarrow CH3 \rightarrow CH2 \rightarrow CH4 SEQ # 2 : CH1 \rightarrow CH3 \rightarrow CH4 \rightarrow CH2 SEQ # 3 : CH1 \rightarrow CH2 \rightarrow CH4 \rightarrow CH3 SEQ # 4 : CH1 \rightarrow CH4 \rightarrow CH3 \rightarrow CH2

SEQ # 5 : CH1 \rightarrow CH4 \rightarrow CH2 \rightarrow CH3

Floating = resistance greater than $160k\Omega$ = SEQ#5

The power on sequence of CH1 to CH4 is shown below:

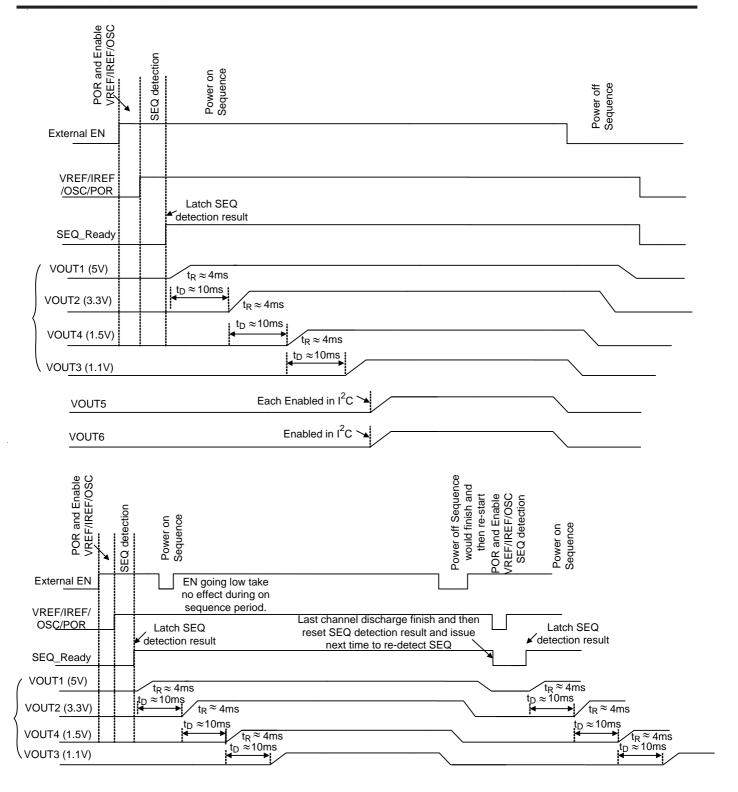
(Using SEQ #3 : CH1 \rightarrow CH2 \rightarrow CH4 \rightarrow CH3 to explain)

When EN1234 goes high, CH1 will be turned on first then CH2 will be turned on after CH1 turn on for 10msec, likewise, CH4 will be turned on after CH2 turns on for 10msec. Finally, CH3 is turned on after CH4 turns on for 10msec. The softstart time is 4msec for each channel.

The power off sequence of CH1 to CH4 is:

When EN1234 goes low, CH3 will turn off first and internally discharge output via LX3 pin. When FB3 < 0.1V, CH4 will turn off and also internally discharge output via the LX4 pin. When FB4 < 0.1V, CH2 will turn off and internally discharge output via the LX2 pin. Likewise, when FB2 < 0.1V, CH1 will turn off and discharge output. After FB1 < 0.1V, CH1 to CH4 shutdown sequence is completed.





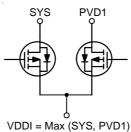
During On sequence period, EN going low would not take effect. After the sequence finish, EN state would be re-checked and decide to keep on or start off sequence.

During Off sequence period, EN going high would not take effect. After the sequence finish, EN state would be re-checked and decide to keep off or start on sequence.



VDDM Bootstrap

To support bootstrap function, the RT5021 provides a power selection circuit which selects the maximum voltage between SYS and PVD1 to support the power requirement at node VDDI. The RT5021 includes UVLO circuits to monitor VDDI and SYS voltage status.



Charger Unit

The RT5021 includes a Li-ion battery charger with Automatic Power Path Management. The charger is designed to operate in below modes:

▶ Pre-Charge Mode

When the output voltage is lower than 2.8V, the charging current will be reduced to a ratio of the fast-charge current set by A8.ISETA [3:0] to protect the battery life-time. The timing diagram is showed in Figure 3.

▶ Fast-Charge Mode

When the output voltage is higher than 3V, the charging current will be equal to the fast-charge current set by A8.ISETA [3:0] shown as Figure 3.

▶ Constant Voltage Mode

When the output voltage is near 4.2V and the charging current falls below the termination current for a deglitch time of 25ms, the charger will be disabled and CHG will go high. The timing diagram is showed in Figure 3.

▶ Re-Charge Mode

When the chip is in charge termination mode, the charging current gradually goes down to zero. Once the battery voltage drops to below 4.1V for a deglitch time of 100ms, the charger will resume charging shown as Figure 3.

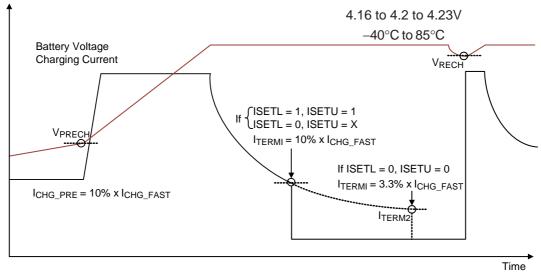


Figure 3



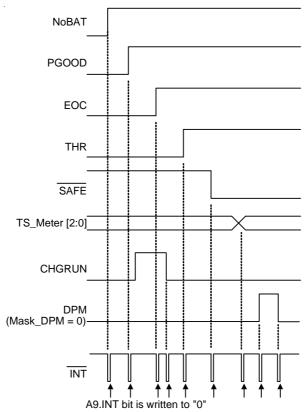
Interrupt Indicator

The RT5021 provides an interrupt indicator output pin (INT). INT is an open drain output which is controlled by A9.INT bit. When the PGOOD, TS_Meter [2:0], EOC, THR, SAFE, NoBAT, CHGRUN, DPM status bits toggle, the A9.INT bit will be set to high. In order to reset the interrupt status, a "0" must be written to the A9.INT bit or power on the PMU again. The timing diagram is shown below:

Interrupt vs. Events (I²C Status Bits)

INT assert		s on with event dition	During PMU on		
(Turn to low)	No Event (0)	Event has occurred (1)	Event appear (0 → 1)	Event disappear $(1 \rightarrow 0)$	
PGOOD	No	Yes	Yes	Yes	
NoBAT	No	Yes	Yes	Yes	
TS_METER [2:0] = 000 (Event may be cold or hot, VP UVLO, NoBAT)	No	Yes	Yes	Yes	
EOC	No	Yes	Yes	Yes	
THR	No	Yes	Yes	Yes	
SAFE	No	Yes	Yes	Yes	
DPM	No	Yes	Yes	Yes	
CHGRUN	No	No	No	Yes	

INT vs. Fault/Status Timing Diagram



When the A9.INT bit is written to "0", the INT will be set to high.

When Mask_DPM = 1 and DPM event change, the INT would not be asserted.



Battery Installation Detection

RT5021 also detects TS voltage to monitor the battery status. If PMU is enabled but TS voltage > 90% of VP node voltage, RT5021 sets the bit

NoBAT = 1 an I^2 C register A10.NoBAT and sets A9.INT bit to "1".

NoBAT	1	No Battery Installed (TS > 90% of VP)
INODAT	0	BAT Installed

VIN Power Good Status

	0	VIN < VUVLO					
PGOOD	0 VUVLO < VIN < VBAT + VOS_L						
PGOOD	1	VBAT + VOS_H < VIN < VOVP					
	0	VIN > VOVP					

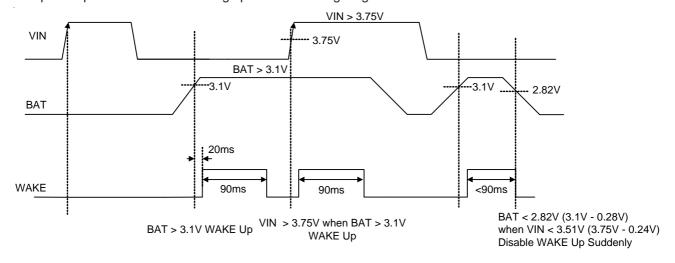
End_Of_Charge (EOC) Status

The bit EOC in I²C register A10.EOC can show the EOC status. If EOC = 1, the charger is in EOC state and A9.INT bit is set to "1"

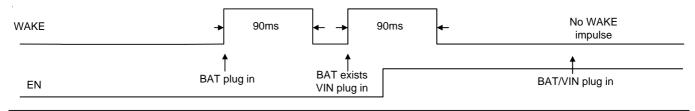
FOC	1	Charging Done or Recharging after Termination
EOC	0	During Charging

Wake-Up Detector

Wake-Up Detector detects VIN or BAT plug-in events. Once BAT plugs in or VIN plugs in for a 19msec deglitch time, the WAKE pin will provide a 90ms width high pulse. The timing diagram shows as below.



When PMU is enabled, WAKE UP impulse would be masked off. WAKE impulse width 90ms can not be cut by EN = H





Suspend Mode

When USUS = 1, the charger will enter Suspend Mode. In Suspend Mode, CHG pin is high impedance and IUSUS(MAX) < 300μA.

Charging Current Decision

The charge current can be set according to the I²C register A8.ISETA [3:0] setting:

	RT5021 value is		set the	battery charge	current le	evel and the list	as belo	w. The default
	Code	BAT Charge Current	Code	Code BAT Charge Code Current Code Current Code			BAT Charge Current	
ISETA [3:0]	0000	0.1A	0001	0.2A	0010	0.3A	0011	0.4A
	0100	0.5A	0101	0.6A	0110	0.7A	0111	0.8A
	1000	0.9A	1001	1A	1010	1.1A	1011	1.2A
	1100	1.2A	1101	1.2A	1110	1.2A	1111	1.2A

Fault-Time

During the fast charge phase, several events may increase the charging time.

For example, the system load current may have activated the APPM loop which reduces the available charging current or the device has entered thermal regulation because the IC junction temperature has exceeded T_{REG}.

However, once the duration exceeds the fault-time, the CHG output pin will flash at approximately 4Hz to indicate a fault condition and the charge current will be reduced to about 1mA.

There are four methods to release the Fault-time:

- ▶ Re-plug power
- ▶ Toggle EN
- ▶ Enter/exit suspend mode
- Remove Battery
- OVP

The fault-time is inverse proportional to the charger current.

Fault-Time α Incharge

Example:

If the sensing battery temperature is hot or cold, the charge current will reduce to half charge current. So, the fault-time will increase to be double.

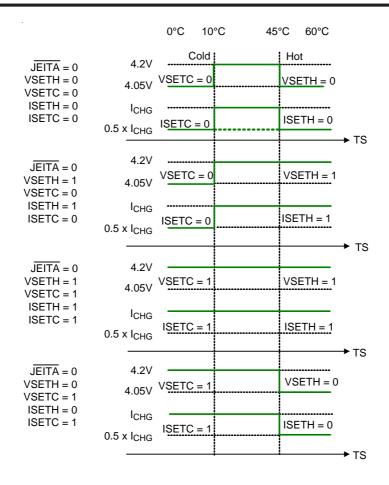
JEITA Battery Temperature Standard

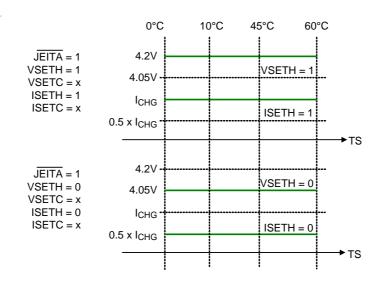
CV regulation voltage will be changed in the following battery temperature ranges: 0°C to 10°C and 45°C to 60°C.

This function can be disabled by A9.VSETH and A9.VSETC.

CC regulation current will be changed in the following battery temperature ranges: 0°C to 10°C and 45°C to 60°C.

This function can be disabled by A9.ISETH and A9.ISETC.







Battery Pack Temperature Monitoring

The battery pack temperature monitoring function can be realized by connecting the TS pin to an external Negative Temperature Coefficient (NTC) thermal resistor to prevent over temperature condition. Charging is suspended when the voltage at the TS pin is out of normal operating range. The internal timer is then paused, but the value is maintained.

When the TS pin voltage returns to normal operating range, charging will resume and the safe charge timer will continue to count down from the point where it was suspended. Note that although charging is suspended due to the battery pack temperature fault, the $\overline{\text{CHG}}$ pin will flash at 0.5Hz and indicate charging.

The 3.3V at VP pin is buffered by the RT5021 once it is in charging state or its PMU part is enabled. If a $100k\Omega$ NTC thermal resistor is used, the A0.TSSEL bit should be set to "1". If a $10k\Omega$ NTC thermal resistor is used, the A0.TSSEL bit should be set to "0". The TSSEL bit determines the TS threshold levels for 0°C and 60°C. It also defines the TS threshold levels used in JEITA operation. The choosing method of R1 and R2 to meet battery temperature monitoring shows as below.

Case 1 : TSSEL = H (For $100k\Omega$ NTC) :

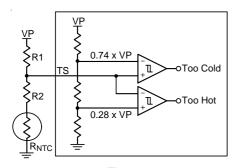


Figure 4

Case 2 : TSSEL = L (For $10k\Omega$ NTC) :

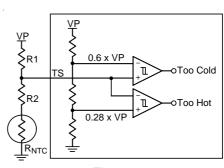


Figure 5

Too Cold Temperature

 $R_{COLD} = R_{NTC}$

Too Hot Temperature

 $R_{HOT} = R_{NTC}$

Form (3)

 $R1 = \frac{R_{COLD}}{0.6} - R_{COLD}$

Too Cold Temperature

 $R_{COLD} = R_{NTC}$

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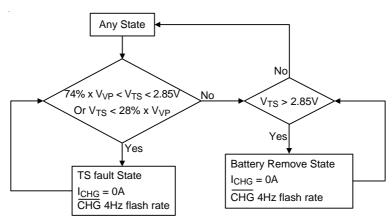
 $R1 = \frac{R_{COLD}}{0.74} - R_{COLD}$



The Control Temperature Used in JEITA Operation

The above calculation gives R1 and R2. JEITA control thresholds for full charging current and 4.2V regulation voltage are at TS/VP ratio = 32% and 52% (for TSSEL = L), 35% and 64% (for TSSEL = H). With the ratio, the corresponding NTC thermistor resistances from the resistors in the voltage divider circuit can be obtained. According to the NTC resistances, the corresponding temperatures can be found. The two temperatures are the control temperatures used in JEITA operation.

Operation State Diagram for TS Pin (TSSEL = H)



Power Switch

For the charger, there are three power scenarios:

- When a battery and an external power supply (USB or adapter) are connected simultaneously If the system required load exceeds the input current limit, the battery will be used to supplement the current to the load. However, if the system load is less than the input current limit, the excess power from the external power supply will be used to charge the battery.
- When only the battery is connected to the system The battery provides the power to the system.
- When only an external power supply is connected to the system The external power supply provides the power to the system.

Input DPM Mode

For the charger, the input voltage is monitored when USB100 or USB500 is selected. If the input voltage is lower than VDPM, the input current limit will be reduced to stop the input voltage from dropping further. This can prevent the IC from damaging improperly configured or inadequately designed USB sources.

If VIN charger type is detected as SDP, the DPM function always is enabled.

For other types, the DPM function always is disabled but user can set A0.ENDPM to turn on the DPM function.

	Enable the charger VIN DPM function. But if VIN charger type is detected as SDP (CHG_TYP [2:0] = 000), the DPM function always is enabled.
ENDPM	0 : VIN DPM function disabled.
	1 : VIN DPM function enabled.

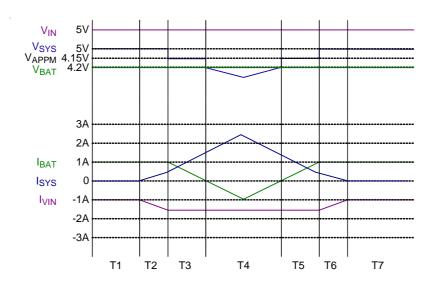


APPM Mode

Once the sum of the charging current and system load current is higher than the maximum input current limit, the SYS pin voltage will be reduced. When the SYS pin voltage is reduced to V_{APPM}, the RT5021 will automatically operate in APPM mode. In this mode, the charging current is reduced while the SYS current is increased to maintain system output. In APPM mode, the battery termination function is disabled.

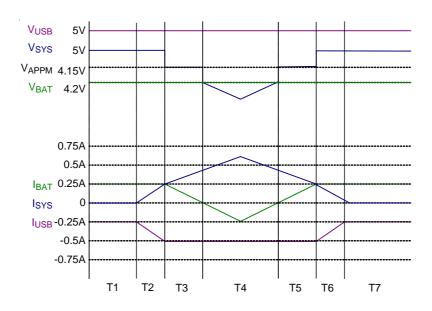
APPM Profile

1.5A Mode:



	I _{SYS}	V _{SYS}	I _{VIN}	I _{BAT}
T1, T7	0	SYS Regulation Voltage	CHG_MAX	CHG_MAX
T2, T6	< I _{VIN_OC} – CHG_MAX	SYS Regulation Voltage	I _{SYS} + CHG_MAX	CHG_MAX
T3, T5	$> I_{VIN_OC} - CHG_MAX < I_{VIN_OC}$	Auto Charge Voltage Threshold	V _{IN_OC}	V _{IN_OC} – I _{SYS}
T4	> I _{VIN_OC}	V _{BAT} – I _{BAT} x R _{DS(ON)}	V_{IN_OC}	I _{SYS} – I _{VIN_OC}

500mA Mode:





	I _{SYS}	I _{SYS} V _{SYS}		I _{BAT}
T1, T7	0	SYS Regulation Voltage	CHG_MAX	CHG_MAX
T2, T6	< I _{VIN_OC} (USB) – CHG_MAX	SYS Regulation Voltage	I _{SYS} + CHG_MAX	CHG_MAX
T3, T5	> I _{VIN_OC} (USB) - CHG_MAX < I _{VIN_OC} (USB)	Auto Charge Voltage Threshold	I _{VIN_OC} (USB)	I _{VIN_OC} (USB) – I _{SYS}
T4	> I _{VIN_OC} (USB)	V _{BAT} – I _{BAT} x R _{DS(ON)}	I _{VIN_OC} (USB)	I _{SYS} – I _{VIN_OC} (USB)

Battery Supplement Mode Short Circuit Protect

In APPM mode, the SYS voltage will continue to drop if the charge current is zero and the system load increases beyond the input current limit. When the SYS voltage decreases below the battery voltage, the battery will kick in to supplement the system load until the SYS voltage rises above the battery voltage.

While in supplement mode, there is no battery supplement current regulation. However, a built-in short circuit protection feature is available to prevent any abnormal current situation. While the battery is supplementing the load, if the difference between the battery and SYS voltage exceeds the short circuit threshold voltage, SYS will be disabled. After a short circuit recovery time, t_{SHORT R}, the counter will be restarted. In supplement mode, the battery termination function is disabled. Note that the battery supply mode exiting condition is $V_{BAT} - V_{SYS} < 0V$.

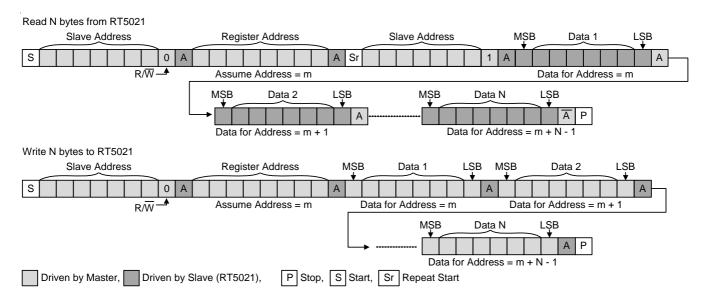
Thermal Regulation and Thermal Shutdown

The charger provides a thermal regulation loop function to monitor the device temperature. If the die temperature rises above the regulation temperature, T_{REG}, the charge current will automatically be reduced to lower the die temperature. However, in certain circumstances (such as high VIN, heavy system load, etc) even with the thermal loop in place, the die temperature may still continue to increase. In this case, if the temperature rises above the thermal shutdown threshold, T_{SD}, the internal switch between VIN and SYS will be turned off. The switch between the battery and SYS will remain on, however, to allow continuous battery power to the load. Once the die temperature decreases by ΔT_{SD} , the internal switch between VIN and SYS will be turned on again and the device returns to normal thermal regulation. The internal thermal feedback circuitry regulates the die temperature to optimize the charge rate for all ambient temperatures.

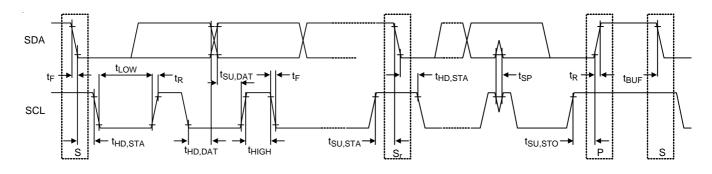


I²C Interface

RT5021 I²C slave address = 0010010 (7 bits). I²C interface supports fast mode (bit rate up to 400kb/s). The write or read bit stream $(N \ge 1)$ is shown below:

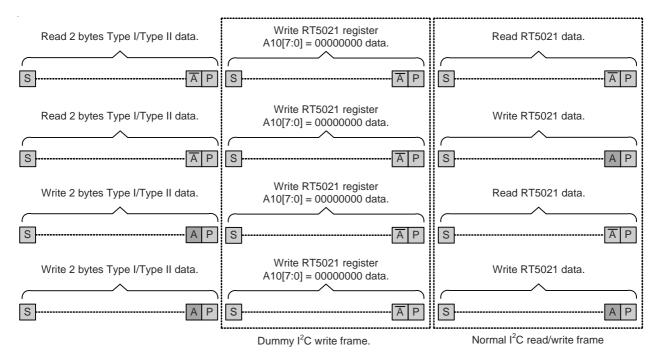


I²C Waveform Information



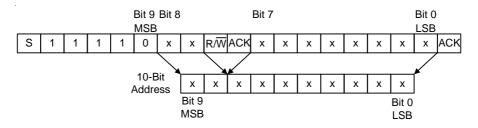


When RT5021 and other I²C devices with 10-bit slave addressing (type I) or two-byte register addressing (type II) coexist in one I²C bus, RT5021 need one dummy I²C write frame to reset the RT5021 internal I²C operation state. The below shows a dummy write frame example, that is to write RT5021 register A10 [7:0] = 00000000. Master should ignore the write operation (This operation is invalid). After the dummy frame, the master can read/write formal I²C frame for RT5021 to get right operation.



Type I: 10-bit slave address data format

In 10-bit addressing, the slave address is sent in the first two bytes. The first byte begins with the special reserved address of 11110XX which indicates that 10-bit addressing is being used.



Type II: 2-byte register address data format

The register address is combined with 2-byte as below.





I²C Register File

Address Name	Regis	ter Address	Bit7 (MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (LSB)
		Meaning	RST_P	RST_C	OVP7	Reserved	ENDPM	TSD	MOD7	TSSEL
A0	0x00	Default	1	0	0	X	0	0	0	1
		Read/Write	R/W	R/W	R/W		R/W	R/W	R	R/W
	RST_	P	RT5021 wo conditions: 1) VDDI < 2) (EN pin In the 2 nd co PMU-relate 0: Don't res	1.3V = low and ondition, R d registers set register	A0.RST_ T5021 use are reset (0x3 to 0	P = 1) es the regist or not wher	er bit A0.R	ST_P to		
	RST_	С	RT5021 wo conditions: 1) VIN < 4 2) VDDI < 3) (BAT < In the 3 rd co Charge-rela 0: Don't res	Reset register (0x3 to 0x6). 5021 would reset Charge-related register under any one of the below three						
			CH7 allow user to select the OVP level by I ² C interface							
	OVP.	7	0 : 16V OVP 1 : 25V OVP							
	ENDP	M	Enable the charger VIN DPM function. But if VIN charger type is detected as SDP (CHG_TYP [2:0] = 000), the DPM function always is enabled. 0: VIN DPM function disabled							
	TSD		I : VIN DPM function enabled. Report whether thermal shutdown of PMU ever occurs. Reset it by writing 0 into the bit or (VDDI < 1.3V). O : Thermal Shutdown has not occurred. 1 : Thermal Shutdown event ever occurs.							
			Report the							
	MOD	7	0 : Current			-				
			1 : Boost.							
			TS/VP ratio							
	TSSE	:L	0 : TS/VP =		<u> </u>					
			1 : TS/VP =	74% (0°C), 28% (60)°C)				



Address Name	Regis	ster Address	Bit7 (MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (LSB)	
		Meaning	ERR1	ERR2	ERR3	ERR4	ERR5	ERR6	ERR7	ERR8	
A1	0x01	Default	0	0	0	0	0	0	0	0	
		Read/Write	RW	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
	204 (Report wh Reset it by					8 ever oc	curs resp	ectively.	
ERR1 to ERR8		0 : No protection event occurs.									
				1 : Protection event ever occurs.							

Address Name	Reg	ister Address	Bit7 (MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	(LSB)		
		Meaning	EN5	EN6	EN8		Е	N7_DIM7	[4:0]		
A2	0x02	Default	0	0	0	0	0	0	0	0	
		Read/Write	RW	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
			Enable/disa	ble CH5							
	EN	15	0 : Disable								
			1 : Enable								
			Enable/disable CH6								
	EN	16	0 : Disable								
			1 : Enable								
			Enable/disa	ble CH8							
	EN	18	0 : Disable								
			1 : Enable								
				Enable CH7 and define FB7 regulation voltage							
E	N7 DIN	Л7 [4:0]	00000 : CH7 turn off								
		1	00001 to111111 : CH7 turn on and dimming ratio : VFB7 = EN7_DIM7 [4 : 0] / 31 x 0.25V								



Address Name	Regis	ster Address	Bit7 (MSB)	Bit6	Bit5	Bit4	Rit3 Rit2 Rit1			Bit0 (LSB)
		Meaning	PSM1	PSM2	PSM3 PSM4 VOUT8 [3:0]					
A3	0x03	Default	1	1	1	1	1	1	0	0
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
			Define the	e CH1/2/3/	4 CCM or	PWM/PSM	switching o	peration.		
PS	PSM1 to PSM4		0 : Force PWM							
			1 : Automatic PWM/PSM switch operation							
			CH8 regu 2.8V.	ılation volta	age can b	e selected	by I ² C inte	rface. The	e default	voltage is
			Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage
\	/OUT8	[3:0]	0000	Switch	0001	1.1V	0010	1.2V	0011	1.3V
		0100	1.4V	0101	1.5V	0110	1.6V	0111	1.7V	
		1000	1.8V	1001	2V	1010	2.2V	1011	2.5V	
			1100	2.8V	1101	3.1V	1110	3.2V	1111	3.3V

Address Name	Regis	ster Address	Bit7 (MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	Bit	Bit0 (LSB)		
		Meaning		VOUT	1 [3:0]		EN1		FB2 [2:0]			
A4	0x04	Default	1	0	1	0	0	1	0	0		
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	RW	R/W		
			CH1 regu	lation volta	age can be	selected b	y I ² C interfa	ace. The d	efault volt	age is 5V.		
			Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage		
	OUT1	[3.0]	0000	3.6V	0001	3.7V	0010	3.8V	0011	3.9V		
v	0011	[5.0]	0100	4V	0101	4.5V	0110	4.6V	0111	4.7V		
			1000	4.8V	1001	4.9V	1010	5V	1011	5.1V		
	1100 5.2V 1101 5.3V Enable/Disable CH1 when sequence ID						1110	5.4V	1111	5.5V		
	EN1	l		equence. (it EN1.		er on/off se equence co	equence. ontrol and o	n/off by the	e pin EN,	not by the		
			1 : Enable									
			FB2 regu 0.8V.	lation volta	age can b	e selected	by I ² C inte	erface. The	e default	voltage is		
			Code	VREF	If Targe	et = 1.8V	If Targe	et = 1V	If Targe	et = 3.3V		
			000	0.72V	1.6	52V	0.9	V	2.9	97V		
			001	0.74V		65V	0.92	25V	3.05	525V		
			010	0.76V		71V	0.9			35V		
			011	0.78V		55V	0.97			175V		
			100	0.8V		8V	1\		3.	3V		
			101	0.82V		45V	1.02		3.3825V			
			110	0.84V		39V				3.465V		
			111	0.86V	6V 1.935V 1.075V			3.54	475V			

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Address Name	Regis	ter Address	Bit7 (MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (LSB)			
		Meaning	FLST	ı	FB3 [2:0]		FLST2		FB4 [2:0]				
A5	0x05	Default	1	1	0	0	1	1	0	0			
		Read/Write	R/W	R/W	RW	R/W	R/W	R/W	R/W	R/W			
			Used to cont	rol the CHO	G pin statu	s when t	he register	bit A9. C	HGSTEN :	= 0.			
	FLS1	Г	1 : CHG = Hi	gh impeda	nce.								
			0 : CHG = Lc	W.									
			FB3 regulation 0.8V.	on voltage	can be se	elected I	oy I ² C inter	face. The	e default v	oltage is			
			Code	VREF	If Target	= 1.8V	If Targe	t = 1V	If Targe	t = 3.3V			
			000	0.72V	1.62	2V	0.9	V	2.97V				
			001	0.74V	1.66	5V	0.92	5V	3.0525V				
	FB3 [2	:0]	010	0.76V	1.71V 0.95V				3.13	35V			
			011	0.78V	1.75	5V	0.975V		3.21	75V			
			100	0.8V	1.8V		1V		3.3	3V			
			101	0.82V	1.845V 1.025V		3.38	25V					
			110	0.84V	1.89V 1.05V			3.46	65V				
			111	0.86V 1.935V 1.075V				3.54	75V				
			Used to control the CHG2 pin status when the register bit A8. CHG2STEN = 0.										
	FLST	2	1 : CHG2 = High impedance.										
			0 : CHG2 = L	.ow.									
			FB4 regulation 0.8V.	on voltage	can be se	elected I	oy I ² C inter	face. The	e default \	oltage is			
			Code	VREF	If Target	= 1.8V	If Targe	t = 1V	If Targe	t = 3.3V			
			000	0.72V	1.62	2V	0.9	V	2.9	7V			
			001	0.74V	1.66	5V	0.92	5V	3.05	25V			
	FB4 [2:0]		010	0.76V	1.71	IV	0.95	5V	3.13	35V			
			011	0.78V	1.75	5V	0.97	5V	3.21	75V			
			100	0.8V	1.8	V	1V	'	3.3	3V			
			101	0.82V	1.84	5V	1.02	5V	3.38	25V			
			110	0.84V	1.89	V	1.05	5V	3.465V				
			111	0.86V	1.93	5V	1.07	5V	3.54	75V			



Address Name	Regis	ter Address	Bit7 (MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (LSB)	
		Meaning		VOUT	5 [3:0]		VOUT6 [3:0]				
A6	0x06	Default	1	0	0	0	0	0	1	1	
		Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W	
			CH5 regulation 1.8V.	ulation volt	age can b	e selected	l by I ² C in	terface. Th	ne default	voltage is	
				Voltage	Code	Voltage	Code	Voltage	Code	Voltage	
			0000	REF	0001	1.1V	0010	1.2V	0011	1.3V	
V	VOUT5 [3:0]			1.4V	0101	1.5V	0110	1.6V	0111	1.7V	
			1000	1.8V	1001	2V	1010	2.2V	1011	2.3V	
			1100	2.5V	1101	2.6V	1110	2.7V	1111	2.8V	
				OUT5 [3:0] lation targ			ns using e	external fee	dback ne	twork and	
			CH6 regul	ulation volt	age can b	e selected	l by I ² C in	terface. Th	ne default	voltage is	
			Code	Voltage	Code	Voltage	Code	Voltage	Code	Voltage	
V	VOUT6 [3:0]			Switch	0001	1.1V	0010	1.2V	0011	1.3V	
				1.4V	0101	1.5V	0110	1.6V	0111	1.7V	
				1.8V	1001	2V	1010	2.2V	1011	2.5V	
				2.8V	1101	3.1V	1110	3.2V	1111	3.3V	



Address Name	Regis	ster Address		Bit7 MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (LSB)		
		Meaning			TIMER	[3:0]		ENCH	USUS	ISETU	ISETL		
A7	0x07	Default		0	1	0	0	0	0	0	0		
		Read/Write		RW	RW	R/W	R/W	R/W	R/W	R/W	RW		
1	IMER	[3:0]	Fa:	st charg urs.		ut time =	(TIMER [3:0] + 1) h		default vo	ltage is 5		
			En	able cha	arger								
	ENC	Ħ	0 :	0 : Enable charger									
			1 : Disable charger										
			VII	N Suspe	nd control								
	USU	S	0 :	No susp	pend								
			1:	Suspen	d								
			VII	N Currer	nt limit sett	ing:		_					
				ISETL	ISETU		Input nt Limit						
				0	0	95mA ((default)						
ISF	TU and	ISETL	0 1 475mA										
	i o ano	. 102 12		1	0	1	Α						
				1	1	1.	5A						
	Note: When Charger Type Detection finds the charger is Dedicated Charging F (Sony or Apple Charger), ISETU/ISETL would set to be 475mA automatically.								rging Port				

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Address Name		egister ddress	Bit7 (MSB)	Bit6	Bit5		Bit4	Bit3	Bit2	Bit1	Bit0 (LSB)
		Meaning	TSH	T[1:0]	Mask_D	РМ	CHG2STEN		ISE	TA [3:0]	
A8	0x08	Default	0	0	0		1	0	1	0	0
		Read/Write	R/W	R/W	R/W		R/W	R/W	R/W	R/W	R/W
			Set TS/\	P thresho	old to mon	itor	battery temp	erature f	or HOT bo	oundary.	
			01-	TS/VP	Equ	uiva	lent Battery	Temper	ature		
			Code	ratio	1	0k 1	NTC	100k	NTC		
Т	SHT [1	:0]	00	28%		60°	C	60)°C		
			01	28.5%		58°	°C	59	9°C		
			10	29%		56°	°C	57	r°C		
			11	29.5%		54°	°C	56	S°C		
			Mask DF	PM functio	n		•				
M	lask_D	PM	0 : Wher	DPM eve	ent change	e, ĪN	IT would be a	asserted.			
			1 : Wher	DPM eve	ent change	e, ĪN	IT would not	be asser	ted.		
			Used to	control Ch	HG2 pin st	tatus	S.				
			0 : See F	LSH2 set							
			1 : Base	on chargi	ng status.						
						011	00075N 4	CHG2	STEN = () (A8.bit4 =	0)
			CI	narging St	atus			FLS	Γ2 = 1 it3 = 1)	FLST2 = (A5.bit3 =	
CI	HG2ST	EN		No Chargii harging Fi		High impedance (No flashing)		`	,		,
				Pre-Charg	je/		Low				
			l	Fast Char	_				igh dance	Low	
				ormal (Fau eout, in the				Impo	danoc		
			l I	ation, batt		4	Hz (0.25s)				
			С	old or too	hot						
				allows us ault value i		the	battery char	ge current level and the			as below.
				BAT	_		BAT		BAT		BAT
ıc	SETA [R ∙∩1	Code	Charge Current	1		Charge Current	Code	Charge Current		Charge Current
10	ν ∟ ι Λ [ν	J.O]	0000	0.1A	0001		0.2A	0010	0.3A	0011	0.4A
			0100	0.5A	0101		0.6A	0110	0.7A	0111	0.8A
			1000	0.9A	1001		1A	1010	1.1A	1011	1.2A
			1100	1.2A	1101		1.2A	1110	1.2A	1111	1.2A



Address Name	Regis	ter Address	Bit7 (MSB)	Bit6	Bit5	Bit4	В	it3	Bit2		Bit1	Bit0 (LSB)
		Meaning	JEITA	VSETH	VSET	C ISETH	ISE	ETC	CHGST	EN	INT	DPM
A9	0x09	Default	0	0	0	0		0	1		0	0
		Read/Write	R/W	R/W	R/W	R/W	R	/W	R/W	1	R/W	R
			BAT char	ge current	and reg	ulation volta	ge co	ntrol	scheme.			
	ITA, VS	СТ	JEITA = (), it means	the cha	rger operation	n is a	autom	atic (JEIT	A ru	le).	
		H, ISETC	and set		TC to	VSETH/VS decide the					_	_
			Used to d	ontrol CHO	G pin sta	tus.						
			0 : See F	LSH set.								
			1 : Base	on chargin	g status.							
						CHOCTEN	,	CHG	STEN = (0 (A9).bit2 = 0))
			Charging Status $CHGSTEN = 1$ $(A9.bit2 = 1)$ $FLST = 1$ $FLST = 0$									
			(A5.bit7 = 1) $(A5.bit7$.bit7 = 0)	
	CHGST	EN	No Charging/ Charging Finish			High impeda (No flashin						
				re-Charge/ ast Charge		0.5Hz (2s)		ligh		Low	
			Abnormal (Fault timer timeout, in thermal regulation, battery too cold or too hot									
	INT		When into	errupt evei	nts happ	en d <u>rain</u> por en, INT port sor must writ	goes	s low a	and this b	oit A9). I <u>NT w</u> o	ould be
			0 : INT =	High								
			1 : INT =									
					-	VIN DPM stated			neans the	e cha	rger DP	M (VIN
			0 : VIN D	PM not act	tivated.							
	DPM		1 : VIN D	VIN DPM activated (working).								
			0. If it is d		T would	t would chec be asserted				•		



Address Name	Regis	ter Address	Bit7 (MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (LSB)	
		Meaning	TS ₋	_METER [2	2:0]	NoBAT	EOC	PGOOD	THR	SAFE	
A10	0x0A	Default	0	0	0	0	0	0	0	0	
		Read/Write	R	R	R	R	R	R	R	R	
TS.	_METE	R [2:0]	Note: wh	TS Meter [2:0] = 110 nen PMU	0°C 1 TS Meter [2:0] = 100 turns on, i	TS Meter [2 10°C TS Mete [2:0] = 00 t would ch	45°C r TS Mete 0 [2:0] = 00	60°C TS Met [2:0] = 0 eter [2:0] a	er (VP 11 TS N	< 0.8V (UVLO) leter [2:0] = 010 TS	
	NoBA	T	Means the 0 : BAT Ir 1 : No Ba	e battery in stalled tery Instal	nstalled or	not. 90% of VP))	DAT and or	ampara ta	the value	
			Note: when PMU tums on, it would check the bit NoBAT and compare to the value 0. If it is different, INT would be asserted. After PMU is on, once NoBAT bit toggles, INT also asserts again. End of charge (EOC) bit show the charge status. If EOC = 1 means the charger is in EOC status.								
			0 : During								
	EOC	;			r Recharg	ing after Te	ermination				
			Note: whe	en PMU tur erent, INT	rns on, it w	ould check	the bit EO	C and com on, once E			
			PGOOD b	oit means t	the VIN po	wer status		_			
				Input Stat	us	PGOOD	Bit Status				
			\	/IN < VUV	'LO		0				
	PGOC)D		O < VIN < VOS_L			0				
	. 330	-		+ VOS_H VOVP			1				
			Note : wh	it is differ	turns <u>on,</u> it	ould be as		PGOOD a			



	THR bit can be let user to monitor the thermal regulation function is working or not.
	0 : thermal Regulation is not working
THR	1 : thermal Regulation is working
	Note: when PMU turn on, it would check the bit THR and compare to the value <u>0</u> . If it is different, <u>INT</u> would be asserted. After PMU is on, once THR bit toggles, <u>INT</u> also asserts again.
	Charger safety timer status.
SAFE	0 : charger in charging or suspended by thermal loop
	1 : safety timer expired
	Note: when PMU turn on, it would check the bit SAFE and compare to the value 0. If it is different, INT would be asserted. After PMU is on, once SAFE bit toggles, INT also asserts again.

Address Names	Regis	ster Address	Bit7 (MSB)	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0 (LSB)		
		Meaning	CHG_	TYP [2:0]	Reserved	Reserved	CHG_2DET	CHG_1DET	CHGRUN		
A11	0x0B	Default	0	0	0	х	Х	0	1	0		
		Read/Write	R	R	R			R/W	R/W	R		
			The CHG_TYP [2:0] is used to recode the charger type.									
			Code Charger Type Code Charger Type									
CL	HG TYP [2:0] Standard USB CHARGER (SDP) 100 APPLE CHARGER								(1A)			
CF	ול ו_טו	2 [2.0]	001	Son	у СНА	RGER -1	111	DEDICAT	ED CHARGEI	R (DCP)		
			010	Son	у СНА	RGER -2		Charging D	ownstream P	ort (CDP)		
			011 APPLE CHARGER 110 (High current Host/Hu									
	CHG 21	DET		sh CD	P and	DCP). Defa		he secondary s 0. Set this b				
			0 : Seco	ndary	CHAR	GER DETE	CTION DIS	ABLED				
			1 : Seco	ndary	CHAR	GER DETE	CTION ENA	BLE.				
	CHG_1I	DET	is 1 (aut	o-dete	ct char		en VIN plug	mary charger in). Toggle th				
	_		0 : Prima	ary CH	ARGE	R DETECT	ION DISABI	LED.				
			1 : Prima	ary CH	ARGE	R DETECT	ION ENABL	.E.				
			The CHGRUN bit is the charger detector status bit. It means the charger detection is running or not.									
			0 : CHA	RGER	DETE	CTION NO	Γ RUNING.					
	CHGR	UN	1 : CHARGER DETECTION RUNNING.									
			value 1.	If it is	differe	nt <u>, ĪN</u> T wou		he bit CHGR ted. After PM n.				



Address Name		legister Address	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
		Meaning	RST_P	RST_C	OVP7	Reserved	ENDPM	TSD	MOD7	TSSEL
		Default	1	0	0	Х	0	0	0	1
A0	0x00	Read/Write	R/W	R/W	R/W		R/W	R/W	R	R/W
		Reset Condition	А	А	Α	G	Α	А	Н	А
		Meaning	ERR1	ERR2	ERR3	ERR4	ERR5	ERR6	ERR7	ERR8
		Default	0	0	0	0	0	0	0	0
A1	0x01	Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
		Reset Condition	Α	А	А	Α	А	Α	А	Α
		Meaning	EN5	EN6	EN8		EN7	_DIM7 [4:0]	
		Default	0	0	0	0	0	0	0	0
A2	0x02	Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
		Reset Condition	В	В	В	В	В	В	В	В
		Meaning	PSM1	PSM2	PSM3	PSM4		VOUT	3 [3:0]	
		Default	1	1	1	1	1	1	0	0
A3	0x03	Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
		Reset Condition	С	С	С	С	С	С	С	С
		Meaning		VO	UT1 [3:0]		EN1		FB2 [2:0]	
		Default	1	0	1	0	0	1	0	0
A4	0x04	Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
		Reset Condition	С	С	С	С	В	С	С	С
		Meaning	FLST		FB3[2:0]		FLST2		FB4[2:0]	
		Default	1	1	0	0	1	1	0	0
A5	0x05	Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
		Reset Condition	С	С	С	С	С	С	С	С
		Meaning		VO	JT5 [3:0]			VOUT	[3:0]	
		Default	1	0	0	0	0	0	1	1
A6	0x06	Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
		Reset Condition	С	С	С	С	С	С	С	С
		Meaning		TIM	IER [3:0]		ENCH	USUS	ISETU	ISETL
		Default	0	1	0	0	0	0	0	0
A7	0x07	Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
		Reset Condition	D	D	D	D	D	D	D	D



Address Name		egister ddress	Bit7	Bit6	Bit5	Bit4	Bit3	Bit2	Bit1	Bit0
		Meaning	TSHT	[1:0]	Mask_DPM	CHG2STEN		ISETA	[3:0]	
		Default	0	0	0	1	0	1	0	0
A8	0x08	Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W
		Reset Condition	D	D	D	D	D	D	D	D
		Meaning	JEITA	VSETH	VSETC	ISETH	ISETC	CHGSTEN	INT	DPM
		Default	0	0	0	0	0	1	0	0
A9	0x09	Read/Write	R/W	R/W	R/W	R/W	R/W	R/W	R/W	R
		Reset Condition	D	D	D	D	D	D	E	D
		Meaning	TS	S_METER	[2:0]	NoBAT	EOC	PGOOD	THR	SAFE
		Default	0	0	0	0	0	0	0	0
A10	0x0A	Read/Write	R	R	R	R	R	R	R	R
		Reset Condition	I	I	I	I	J	J	J	J
		Meaning	С	HG_TYP	[2:0]	Reserved	Reserved	CHG_ 2DET	CHG_ 1DET	CHGRUN
A11	0x0B	Default	0	0	0	Х	Х	0	1	0
^11	UXUD	Read/Write	R	R	R			R/W	R/W	R
		Reset Condition	К	К	К	G	G	F	F	L

I²C register reset condition:

- A. In addition to A0.bit 1 and A0.bit4, the bits of A0 and A1 (register 0x0, 0x1) reset only when (VRTC < 1.6V).
- B. The bits of A2 (register 0x2) and A4.bit3 reset when (EN pin = low) or (VDDI < 2.4V) or (BAT < 1.3V) or (Temperature > 125°C)
- C. In addition to A4.bit3, PMU settings (A3 to A6, register 0x3 to 0x6) reset when (EN pin = low and A0.RST_P = 1) or (VDDI < 1.3V)

VDDI < 1.3V	EN pin	A0.RST_P bit	==>	Reset PMU Setting
TRUE	х	x (don't care)		Reset
	Low	1		Reset
False (VDDI > 1.3V)	High	1		Not reset
raise (VDDI > 1.3V)	Low	0		Not reset
	High	0		Not reset

D. In addition to A9.bit 1, charger settings (A7 to A9, registers (0x7 to 0x9) reset when (VIN < 4V) or (VDDI < 1.3V) or $((BAT < 3.1V) \text{ and } (A0.RST_C = 1))$



VDDI < 1.3V	VIN > 4V	A0.RST_C bit	(BAT < 3.1V)	==>	Reset Charger Setting
true (VDDI < 1.3V)	Х	х	х		Reset
false (VDDI > 1.3V)	False (VIN < 4V)	х	х		Reset
false (VDDI > 1.3V)	True (VIN > 4V)	1	TRUE		Reset
false (VDDI > 1.3V)	True (VIN > 4V)	1	FALSE		Not reset
false (VDDI > 1.3V)	True (VIN > 4V)	0	TRUE		Not reset
false (VDDI > 1.3V)	True (VIN > 4V)	0	FALSE		Not reset

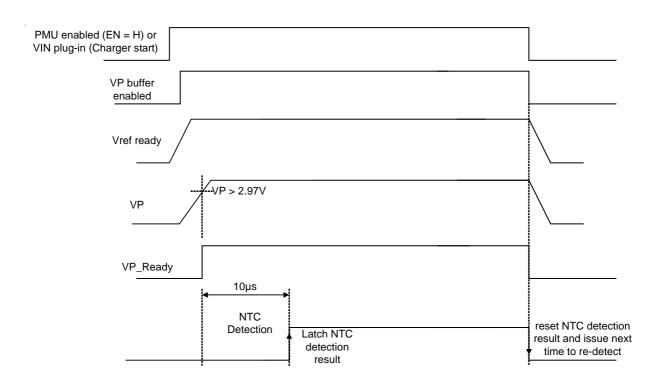
- E. (EN pin = low) or (VDDI < 1.3V)
- F. Charger type detection A11 (registers 0xB) reset when (VIN < 4V) or (VDDI < 1.3V)
- G. Always reset.
- H. A0.bit1 will be reset when (EN pin = low) or (VDDI < 2.4V) or (BAT < 1.3V) or (PMU protection occur) or (Temperature < 125°C).
- I. A0.bit1 will be reset when (EN pin = low) or (VDDI < 2.4V) or (BAT < 1.3V) or (In addition to CH7 OVP, PMU protection occur) or (Temperature < 125°C).
- J. Reference page-54 A10 explanation.
- K. A11.bit7 to bit5 will be rewritten after charging type detects finish.
- L. A11.bit0 keeps high during charging type detecting.

CHG Signal Status

		CHG		CHG2		
Charging Status	CHGSTEN = 1	CHGSTEN = 0		CHG2STEN = 1	CHG2STEN = 0	
	CHOOTEN = 1	A5. bit7 = 1 A5. bit7 = 0	CHOZOTEN = T	A5. bit3 = 1	A5. $bit3 = 0$	
No Charging/Charging Finish	High impedance (No flashing)			High impedance (No flashing)		
Pre-Charge/Fast Charge	0.5Hz (2s)	High		Low	High impedance	Low
Abnormal (Fault timer timeout, in thermal regulation, battery too cold or too hot)	4Hz (0.25s)	impedance	Low	4Hz(0.25s)		



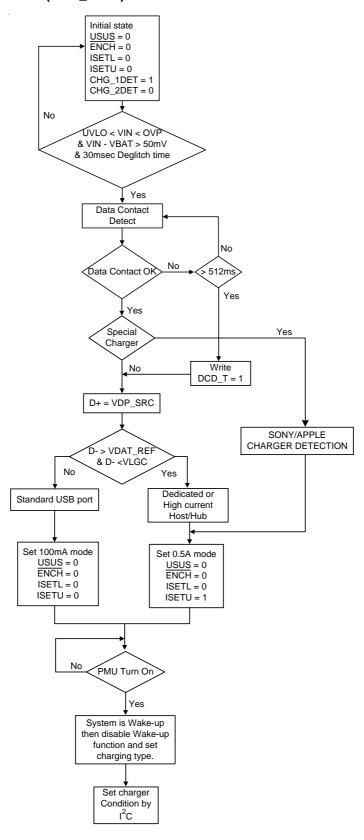
NTC Thermistor Order Detection



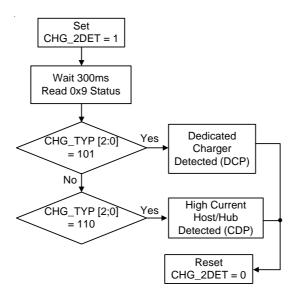


USB Charger Detection

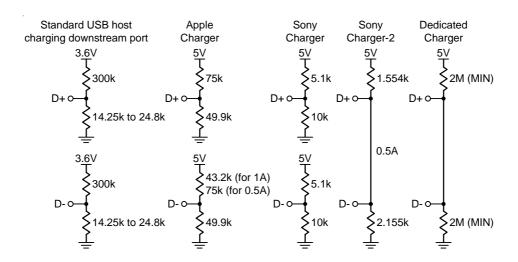
Primary Charger Type Detection (CHG_1DET) : Detection Time ≤ 200ms



Secondary Charger Type Detection (CHG_2DET)



D+/D- impedance of Standard USB Host/Charging Downstream Port. Apple Charger, Sony Charger, and Dedicated Charger:





Thermal Considerations

For continuous operation, do not exceed absolute maximum junction temperature. The maximum power dissipation depends on the thermal resistance of the IC package, PCB layout, rate of surrounding airflow, and difference between junction and ambient temperature. The maximum power dissipation can be calculated by the following formula:

$$P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$$

where T_{J(MAX)} is the maximum junction temperature, T_A is the ambient temperature, and θ_{JA} is the junction to ambient thermal resistance.

For recommended operating condition specifications, the maximum junction temperature is 125°C. The junction to ambient thermal resistance, θ_{JA} , is layout dependent. For WQFN-40L 5x5 package, the thermal resistance, θ_{JA} , is 27.5°C/W on a standard JEDEC 51-7 four-layer thermal test board. The maximum power dissipation at $T_A = 25^{\circ}C$ can be calculated by the following formula:

$$P_{D(MAX)} = (125^{\circ}C - 25^{\circ}C) / (27.5^{\circ}C/W) = 3.64W$$
 for WQFN-40L 5x5 package

The maximum power dissipation depends on the operating ambient temperature for fixed T_{J(MAX)} and thermal resistance, θ_{JA} . The derating curve in Figure 6 allows the designer to see the effect of rising ambient temperature on the maximum power dissipation.

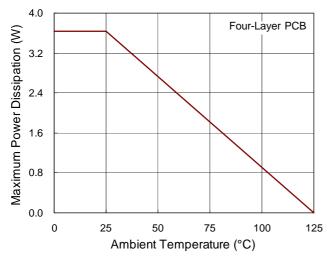


Figure 6. Derating Curve of Maximum Power Dissipation

Layout Consideration

For the best performance of the RT5021, the following PCB layout guidelines must be strictly followed.

- > Place the input and output capacitors as close as possible to the input and output pins respectively for good filtering.
- Keep the main power traces as wide and short as possible.
- The switching node area connected to LX and inductor should be minimized for lower EMI.
- Place the feedback components as close as possible to the FB pin and keep these components away from the noisy devices.
- Connect the GND and Exposed Pad to a strong ground plane for maximum thermal dissipation and noise protection.
- ▶ To make CH1 and whole chip stable, the power path from the PVD1 pin to its output capacitors must be as short (≤ 1mm is better) and wide as possible.
- ▶ To make CH4 and CH5 stable, the power path from the PVD45 pin to its input capacitors must be as short (≤ 1mm is better) and wide as possible.

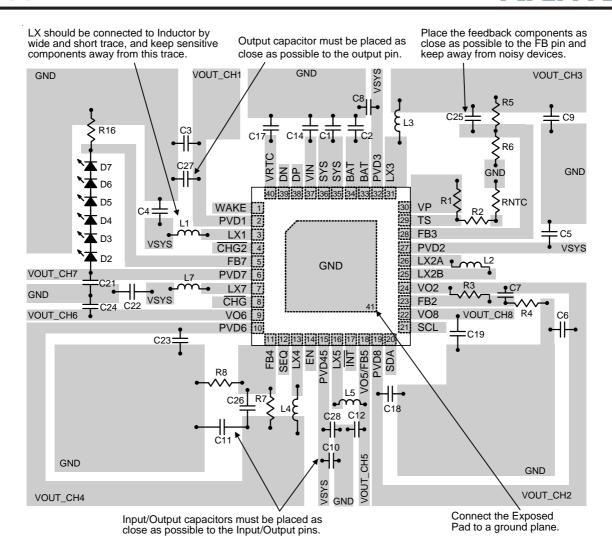


Figure 7. PCB Layout Guide



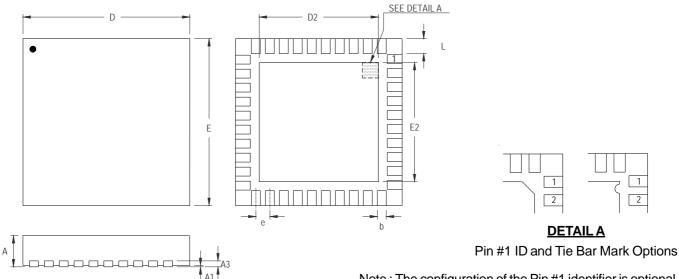
	Protection Type	Threshold (Typical) Refer to Electrical Spec.	Protection Methods	PMU Shutdown Delay Time	Reset Method
SYS	UVLO	SYS < 1.5V	PMU Shutdown.	No-delay	EN1234 pin set to low or SYS > 2.1V
VDDI	OVP	VDDM > 6V	Automatic reset at VDDM < 5.85V	100ms	VDDI power reset or EN1234 pin set to low
	UVLO	VDDM < 2.4V	PMU Shutdown.	No-delay	VDDI power reset or EN1234 pin set to low
	Current Limit	N-MOSFET peak current > 3A	N-MOSFET off, P-MOSFET off. Automatic reset at next clock cycle.	100ms	VDDI power reset or EN1234 pin set to low
	PVD1 OVP	PVDD1 > 6V	N-MOSFET off, P-MOSFET off.	No-delay	VDDI power reset or EN1234 pin set to low
CH1 Step-Up	PVD1 UVP1	PVDD1 < (VSYS – 0.8V) or PVDD1 < 1.28V after soft-start end.	N-MOSFET off, P-MOSFET off.	100ms	VDDI power reset or EN1234 pin set to low
	PVD1 UVP2	After pre-charge (PVD1 UVP-2 : FB1 < 0.4V after pre-charge)	N-MOSFET off, P-MOSFET off	No-delay	VDDI power reset or EN1234 pin set to low
	PVD1 Over Load (OL)	Target – 0.6V Target Voltage is defined in A4.VOUT1 [3:0]	PMU Shutdown when OL occur each cycle until 100ms.	100ms	VDDI power reset or EN1234 pin set to low
	Current limit	Both P-MOSFET (PVD2 – LX2A) and N-MOSFET (LX2B – GND) peak current > 2A	N-MOSFET off, P-MOSFET off. Automatic reset at next clock cycle.	100ms	VDDI power reset or EN1234 pin set to low
CH2	VO2 OVP	PVDD1 > 6V	N-MOSFET off, P-MOSFET off.	No-delay	VDDI power reset or EN1234 pin set to low
Step-Up/Down	FB2 UVP	FB2 < 0.4V after soft-start end.	N-MOSFET off, P-MOSFET off.	No-delay	VDDI power reset or EN1234 pin set to low
	FB2 Over Load	Target – 0.1V (Target voltage is the chosen one in A4.FB2 [2:0])	PMU Shutdown when OL occur each cycle until 100ms.	100ms	VDDI power reset or EN1234 pin set to low
CH3 Step-Down	Current limit	P-MOSFET peak current > 1.8A	N-MOSFET off, P-MOSFET off. Automatic reset at next clock cycle.	100ms	VDDI power reset or EN1234 pin set to low
	FB3 UVP	FB3 < 0.4V after soft-start end.	N-MOSFET off, P-MOSFET off.	No-delay	VDDI power reset or EN1234 pin set to low
	FB3 Over Load	Target – 0.1V (Target voltage is the chosen one in A5.FB3 [2:0])	PMU Shutdown when OL occur each cycle until 100ms.	100ms	VDDI power reset or EN1234 pin set to low



	Protection Type	Threshold (Typical) Refer to Electrical Spec.	Protection Methods	PMU Shutdown Delay Time	Reset Method
CH4 Step-Down	Current limit	P-MOSFET peak current > 1.8A	N-MOSFET off, P-MOSFET off. Automatic reset at next clock cycle.		VDDI power reset or EN1234 pin set to low
	FB4 UVP	FB4 < 0.4V after soft-start end.	N-MOSFET off, P-MOSFET off.	No-delay	VDDI power reset or EN1234 pin set to low
	FB4 Over Load	Target – 0.1V (Target voltage is the chosen one in A5.FB4 [2:0])	PMU Shutdown when OL occur each cycle until 100ms.	100ms	VDDI power reset or EN1234 pin set to low
CH5 Step-Down	Current limit	P-MOSFET peak current > 1.5A	N-MOSFET off, P-MOSFET off. Automatic reset at next clock cycle.	100ms	VDDI power reset or EN1234 pin set to low
	VO5 UVP	PVD5 UVP: FB5 < 0.4V after soft-start end	N-MOSFET off, P-MOSFET off.		VDDI power reset or EN1234 pin set to low
	VO5 Over Load	Target voltage is the chosen one in A6.VOUT5 [3:0] = 0000 (FB5 = 0.8V) Target voltage is the chosen one in A6.VOUT5 [3:0] = 0001 to 0111 Target voltage is the chosen one in A6.VOUT5 [3:0] = 0111 to 1111	PMU Shutdown when OL occur each cycle until 100ms.	100ms	VDDI power reset or EN1234 pin set to low
CH6 LDO	Max. output current (current limit)	P-MOSFET current > 0.45A (PVD6 = 1.5V, VO6 = 1.3V)	P-MOSFET off.	100ms	VDDI power reset or EN1234 pin set to low
CH7 WLED	Current limit (Step-Up mode)	N-MOSFET current > 0.8A	N-MOSFET off, P-MOSFET off. Automatic reset at next clock cycle.	100ms	VDDI power reset or EN1234 pin set to low
	PVDD7 OVP	PVDD7 > 16V (A0.OVP7 = 0) PVDD7 > 25V (A0.OVP7 = 1)	N-MOSFET off, P-MOSFET off. Shutdown CH7 by self	No-delay	VDDI power reset and A2.EN7_DIM7 [4:0] reset or EN1234 pin set to low
CH8 LDO	Max. output current (current limit)	P-MOSFET current > 0.45A (PVD6 = 3V, VO6 = 2.5V)	P-MOSFET off.	100ms	VDDI power reset or EN1234 pin set to low
Thermal	Thermal shutdown	Temperature > 155°C	All channels stop switching	No-delay	Temperature < (155 – 20)°C
I VIN ⊢	VIN UVLO	VIN < 3.3V	No-charge	No-delay	No latch
V114	VIN OVP	VIN > 6.5V	No-charge	No-delay	No latch



Outline Dimension



Note: The configuration of the Pin #1 identifier is optional, but must be located within the zone indicated.

Symbol	Dimensions I	n Millimeters	Dimensions In Inches		
	Min	Max	Min	Max	
А	0.700	0.800	0.028	0.031	
A1	0.000	0.050	0.000	0.002	
А3	0.175	0.250	0.007	0.010	
b	0.150	0.250	0.006	0.010	
D	4.950	5.050	0.195	0.199	
D2	3.250	3.500	0.128	0.138	
Е	4.950	5.050	0.195	0.199	
E2	3.250	3.500	0.128	0.138	
е	0.400		0.016		
L	0.350	0.450	0.014	0.018	

W-Type 40L QFN 5x5 Package

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DS5021-03 September 2022